Kentech Instruments Ltd.

Scorpion-Z X-Ray Streak Camera

Version 1

PLEASE READ THIS MANUAL CAREFULLY BEFORE USING THE CAMERA.



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Figure 1 The tube with the FO fiducial fitted.

1. **DISCLAIMER**

This equipment contains high voltage power supplies. Although the current supply capacity is small, careless use could result in electric shock. It should be noted that as the streak tube is a long way from the supplies the cables can contain significant energy. In many cases the cable live electrodes are protected for fingers ("finger safe") but there are situations where this cannot be achieved. It is assumed that this highly specialised equipment will only be used by qualified personnel.

Kentech Instruments Ltd. accept no responsibility for any electric shock or injury arising from use or misuse of this equipment. It is the responsibility of the user to exercise care and common sense with this highly versatile equipment.

2. SERIAL NUMBERS

There are four main components with serial numbers:

Streak Tube	-1
Rack Electronics	-2
Interface box 1	-3
Interface box 2	-4

3. ABBREVIATIONS

ADC or adc	Analogue to Digital Convertor
AWG	Arbitrary Waveform Generator
BB mode	Blankety blank mode - same as full frame gating
CPLD	Complex programmable logic device
CCD	Charge Coupled Device (camera)
cr	carriage return
DISC	Dim based X-Ray streak camera
DPCO	Double Pole Change Over
dv	desired value
EEPROM	Electrically programmable and erasable Read only memory, non-volatile
EHT or eht	Extra High Tension (high voltage)
eof	End of Frame
EPLD	Electrically programmable logic device
EPROM	Electrically programmable read only memory, non-volatile
FET	Field Effect Transistor
FN	Foot Note
FO	Fibre optic
GXD	Gated X-ray Diagnostic
HDISC	Neutron hardened version of DISC
HSLOS	Neutron Hardened Single Line of Sight Imager, also called SLOS2.
hw	hardware
IBC	User's control system, also called UCS.
INT	Intensifier
lf	line feed
LFC	Large Format Camera, Gated X-ray Imager
LLNL	Lawrence Livermore National Laboratory
m	metres (meters US)
MAX	A phosphor and MCP combination
MCP	Micro Channel Plate
MCU	Main Control unit
mv	measured value
PCD	Photo Conductive Detector
PSU or psu	power supply unit
RAM	Random access memory, volatile.
RHIC	Radiation Hardened Instrument Controller
RSCE	Remote Streak Camera Electronics
ro	read only
rw	read and write
SD	Standard Deviation
SLOS2	Alternative name for HSLOS
SW	sweep
SW	software
UCS	Users Control System (to be provided by the user), also called IBC
W/E	Write Enable
wo	write only
w.r.t.	with respect to

4. BILL OF MATERIALS

Quantities are 1 off except where stated.

4.1 **TOP LEVEL ITEMS**

Rack Controller, containing Control module Sweep module Max driver module High Voltage module - not removable. 0030-0252 HDISC Tube Interface box - 2 off

0010-0159 Scorpion-Z Streak camera for the Z machine Sub assembly details 0060-0154 Scorpion-Z Rack unit 0020-0652 Scorpion-Z Backplane 0020-0601 High Voltage PSU module revised from RSCE HV PSU module 0060-0169 Control module for Scorpion-Z Rack controller 0020-0600 RSCE trigger card 0020-0445 Artix AWG card

0060-0170 Sweep module for Scorpion-Z Rack controller 0020-0603 RSCE sweep output card 0020-0602 RSCE sweep main card 0020-0610 Scorpion-Z sweep bias card

0060-0171 Max module for Scorpion-Z Rack controller 0020-0646 Scorpion-Z Max Module card1 based on SPIDER card 0020-0647 Scorpion-Z Max Module card2 based on SPIDER card

0060-0172 HV module for Scorpion Rack controller 0020-0650 Scorpion-Z HV zener card 0020-0649 Scorpion-Z HV control card 0020-0648 Scorpion-Z HV card

0060-0155 Scorpion - Z interface box

Cables

4 off	0070-0161-002 Scorpion-Z HV leads interface box to tube
4 off	0070-0161-004 Scorpion-Z HV leads rack to interface box
1 off	0070-0162-002 Scorpion-Z corrector leads rack to interface box
1 off	0070-0162-004 Scorpion-Z corrector leads interface box to tube
1 off 1 off	0070-0163-002 Scorpion-Z blanking trigger lead rack to interface box 0070-0163-004 Scorpion-Z blanking trigger lead interface box to tube
1 off 1 off	0070-0164-005 Scorpion-Z sweep leads interface box to tube positive 0070-0164-006 Scorpion-Z sweep leads interface box to tube negative
1 off 1 off	0070-0165-005 Scorpion-Z sweep monitor leads tube to interface box positive 0070-0165-006 Scorpion-Z sweep monitor leads tube to interface box negative
1 off	0070-0166-002 Scorpion-Z phosphor leads rack to interface box
1 off	0070-0166-004 Scorpion-Z phosphor leads interface box to tube (max module)
1 off	0070-0166-007 Scorpion-Z phosphor return leads interface box to rack
1 off	0070-0166-009 Scorpion-Z phosphor return leads tube (max module) to interface box
4 off	0070-0167-002 Scorpion-Z MCP leads rack to interface box
4 off	0070-0167-005 Scorpion-Z MCP leads interface box to tube (max module)
1 off	0070-0168 Scorpion-Z HV enabled lead
1 off	0070-0169 Scorpion-Z interlock lead
1 off L	JS style power lead - IEC
Гube	

Streak Tube

0030-0252 HDISC Tube later than XXXX

SMA sweep monitor variant¹

0020-0651 HDISC blanking switch

¹ The standard tube uses Lemo 00.250 connectors for the sweep monitor. These are not easily compatible with a 5mm OD cable requested for this project.

5. HAZARDOUS MATERIALS

Below is a list of construction materials. None is very hazardous. The quantity of lead used is small and only used in hand built electronics and cable connectors. Much of the electronics is not hand built. Hand built electronics using lead free solder has resulted in low reliability and is consequently avoided. Some of the very specialised types of circuit used in this device are not amenable to machine building. The aluminium used in the tube is not coated (Alochrom or Iridite).

5.1 THE TUBE

Aluminium Alloy (the main construction material) PEEK Tantalum (the anode) lead solder used for electrical connections where crimping has proven to be unreliable. copper, cables **PTFE** Silicone rubber, potting but none in vacuum facing parts gold (on connectors) and in the LLNL cathode pack Chromium (plating on connectors) Brass Stainless steel - non magnetic. Nickel (meshes) Epoxy adhesives PCB material (FR4) but none in vacuum facing parts Electronic components but none in vacuum facing parts except a few ceramic resistors. Nitrile rubber (O rings) - all preheat treated - supplied by LLNL Nylon but none in vacuum facing parts

5.2 THE ELECTRONICS

Aluminium Alloy (the main housing) with anodised and Iridite Chromium free conductive coatings lead solder copper, cables PTFE Silicone rubber, potting gold (plating on connectors) Chromium (plating on connectors) Brass Stainless steel epoxy adhesives PCB material (FR4) Electronic components ink

6. INTRODUCTION

This manual describes the operation and use of the Scorpion-Z x-ray streak camera. The camera is based upon a standard Kentech Low magnification tube design with the latest upgrade as the current HDISC tubes, i.e. with the corrector mesh assembly within the grounded lens 2 and a neutron resistant blanking switch. The main electronics package (rack unit) is a 6U x 19 inch rack mount assembly mounted 16m from the tube and is linked by various cables. The software control interface uses similar techniques to the RSCE for control of the unit. The streak tube is designed to be used with a variety of electron sensors but initially set up for use with a customer supplied MAX module. This comprises an MCP for electron detection and multiplication and a phosphor. A CCD camera will need to be fitted to the output of the MAX module. No CCD system is included with this package. The Streak tube can also accept a LLNL type HCMOS camera but no trigger support for such a detector is included with this system.

For users not familiar with X-ray Streak cameras or indeed any streak camera, some information may be found at http://www.kentech.co.uk/tut_xrsc.html and http://www.kentech.co.uk/PDF/Slide_show2003.pdf

6.1 **RECENT CHANGES TO THE STREAK TUBE**

Following requests from customers, materials in the tube that are vacuum facing have been modified. The main issue was to remove solder from vacuum facing components. This has been partially achieved with small design changes that avoid the need to solder components, particularly the high voltage feed-throughs that are now clamped. Some electrical connections have been made by clamping or crimping.

"O" rings have been provided by LLNL and are baked out before fitting. Small amounts of approved vacuum grease (Krytox[™] XHT-ACX) have been used. Silver loaded epoxy has been used to attach the corrector mesh. Hook up wire for the corrector electrode is made from single stranded copper wire covered in PTFE. All vacuum facing components have been degreased prior to assembly and untouched by human hand during assembly.

6.2 SPECIFICATIONS OF THE SYSTEM

The system is designed to operate with the electronics remote (~16m) from the tube. This is mainly achievable but the blanking switch is mounted on the tube and there is also an interface box fairly close to the tube (~2.5m) which contains passive components to help prevent damage to the tube in the event of breakdowns. The cabling between the remote control electronics and the tube can contain enough stored energy to damage tube components in the event of breakdowns. The use of a local interface box with current limiting resistors helps dissipate the energy. It also provides a suitable platform from which to switch from heavy cables to smaller and lighter more flexible ones for local connection. The interface box also contains an RC divider circuit for monitoring the phosphor voltage on Max modules that have a second connection to the phosphor. The Max module supplied for testing did not have such a provision and there is no simple way to check remotely that the phosphor is connected.

Streak tube	Low magnification Kentech design with corrector electrode and mesh. The tube also has independent control of 4 of the lens elements giving control over the magnification.
Photocathode	The system is supplied fitted with a LLNL photocathode pack (supplied by the user).

Overall tube voltage range	0 to -15 kV ²				
Cathode length	>25 mm (28 mm is probably useful)				
Cathode to extraction grid spacing	1 to 5 mm dependent upon spacers and vacuum quality				
Electron detector	The unit is designed for the user to fit their own direct electron bombardment sensor. Kentech can supply an adaptor and a standard phosphor.				
Sweep speeds	The duration of the sweep can be set from ~ 1 ns to ~ 20 ns				
Power requirements	typically 115/240 AC 50/60 Hz.				
Dimensions					
Rack Unit	19 inch rack mount, 6U high x 400 mm deep - plus connectors, front and rear.				
Sweep bias voltage on each plate	-800 V to +800 V				
Maximum repetition rate	Sweep unit >5 Hz but see12.1.2 on page 36				
	The blanking and crowbar circuits are limited by the rate of switch on of the focus voltages. These are ramped up over several seconds. They may only be used in single shot mode.				
Triggers	2 triggers (optical or electrical).				
	Currently both must be of the same type.				
Electrical trigger requirements	5 volts into 50Ω rising in < 5 ns for both triggers.				
Optical trigger sweep	Optical trigger signal input				
	Wavelength 820-900 nm				
	Optical power (on) -15 dBm (min), +3 dBm (max)				
	Optical power (off) -30 dBm (max)				
	Width (50% level) 100 ns (min), 250 ns (max)				
	Rise time <2 ns				
Optical trigger pre trigger	Use Broadcom HFBR-1404Z transmitter or similar.				
Tube connectors					
Photo-cathode	Custom HV connector				
Mesh	Custom HV connector				
Lens 1	Custom HV connector				
Lens 3	Custom HV connector				
Corrector	Lemo ERA.00.250.CTL				
Mating connector	FFB.00.250.CTAC33				
Sweep drives	2 x TNC - use 90° plugs on cables.				
Sweep monitors	2 x SMA - use 90° plugs on cables.				
Blanking drive	Lemo PSA.00.250.CTL.C33				
Mating connector	FFA.00.250.CTA.C33				

2 Low voltages are used for slow turn on. There are 6 kV of zeners between the lens outputs.

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6.3 CABLES AND CONNECTORS

Fielding the Scorpion-Z streak camera will require many leads. Further, as initially proposed, the streak tube was to be at one of two possible locations, the second requiring slightly longer leads for the final stage from the interface box to the tube.

The lead and connector requirements have been captured into two documents that give the details of all the connectors and leads. One document has been a collaborative effort between the user and Kentech Instruments. Further, the rack is to be used within a screened room and a set of leads from the rack to the screened room wall will be needed. These are included in the two documents but are not part of the deliverables with this device. The connections on the outside of the screened room that go to the tube are the same as those on the rack unit. This means that the system can be tested without such leads although there are timing issues for the "MCP off" signal, the blanking trigger and the sweep waveforms.

Figure 3 on page 15, Table 1 on page 16 and Table 2 on page 17 give the details of the connectors and leads required. There are a few points to note:

- 1. For the phosphor monitor to work there need to be two connections to the phosphor. Some Max module heads have this as standard, one either side of the tube. For Max modules with a single connection, a suitable "T" piece/connection could be used to make a second connection but this would not give a true continuity test.
- 2. The phosphor monitor circuit in each of the interface boxes is an RC network that will deliver the phosphor voltage into a $1M\Omega$ load at the end of a long cable. Consequently this can be used either for pulsed or DC mode of the phosphor with a ~2000:1 division ratio. See Figure 14 on page 34.
- 3. The system can check the continuity of the phosphor connection by measuring the current in DC mode. This only works if there is a resistive load to ground at the phosphor. The monitor circuit provides this. If the monitor circuit is not connected to the phosphor no continuity test can be made.
- 4. Note that the cabling for the phosphor is 75Ω , cable except that from the monitor circuit to the scope, which is 50Ω . The 75Ω is used for reduced capacitance. During pulsed mode the charge stored in the pulser is shared between the source and the load. Keeping the load capacitance small results in a higher voltage available on the load.
- 5. The lengths of cables for the MCP drive, blanking trigger and sweep leads are all preset so that the signals arrive at the tube at the correct times with respect to each other. In particular the sweep leads are in foam dielectric cable. This has a faster propagation rate than the other cables and consequently the ramp waveforms are delayed w.r.t. the other signals.



Figure 2 General wiring diagram showing the major blocks and cables

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Cables and connectors between the rack controller and the streak tube, with the rack controller inside a screened box.





Figure 3 Cables and connectors from the rack to the streak tube

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	Scorpion leads and box connectors							
							Supplied	
High Volta	ge leads and conne	ctors (15k	V focus supplies)				Will be required	
Based on o	one rack system, an	d 2 interfa	ce boxes at different location	ns. Tube connecto	rs not indicated.			
Item	Kentech part No.	QTY	use	Cable	Length of cable [feet]	Length of cable [m]	Left connector (nearer tube)	Right connector (nearer rack)
1	0070-0161-001	4	Rack to Screened Room wall	HTV-305-22-2	8	2.438	PSA.3Y.415.CTL.57 used ERA.3Y.415.CTL + custom rear cover	FFA.3Y.415.CTA.57
2	0070-0161-002	4	Radial Control box to Tube	HTV-305-22-2	8	2.438	SMA in house HV	FFA.3Y.415.CTA.C57
4	0070-0161-003	4	Screened room to	HTV-305-22-2	44	13.411	FFA.3Y.415.CTA.C57	FFA.3Y.415.CTL.C57
5	0070-0161-005	4	Screened room to	HTV-305-22-2	44	13.411	FFA.3Y.415.CTA.C57	FFA.3Y.415.CTL.C57
6		12	Rack and Interface					ERA.3Y.415.CTA
7	ł	2	Interface box input					FRA.3Y.415.CTI
Petzval Co	rrector			PC222			Bulkbood jock SHV	
8	0070-0162-001	1	Rack to screened room wall	(replaces RG174)	8	2.438	Pasternack PE44093 or similar	SHV Pasternack PE4194 or similar
9	0070-0162-002	1	Screened room to Radial interface box	RG223	44	13.411	SHV Pasternack PE4194 or similar	SHV Pasternack PE4194 or similar
10	0070-0162-003	1	Screened room to Axial interface box	RG223	44	13.411	SHV Pasternack PE4194 or similar	SHV Pasternack PE4194 or similar
11	0070-0162-004	1	Radial interface box to tube	RG316	8	2.438	FFA.00.250.CTA.C31	SHV Pasternack PE4498 or similar
12	0070-0162-005	1	Axial interface	RG316	20	6.096	FFA.00.250.CTA.C31	SHV Pasternack PE4498 or similar
13		1	Rack and Interface					SHV Pasternack
14		4	Interface box					SHV Pasternack
			input & output					PE4239 or similar
Scorpion-2	Z blanking trigger	1						
15	0070-0163-001	1	Rack to screened room wall	RG316	8	2.438	jack PE4106 or similar	BNC plug for RG316
16	0070-0163-002	1	Screened room to Radial interface box	RG223	44	13.411	BNC plug for RG223+ BLUE STRAIN RELIEF	BNC plug for RG223+ BLUE STRAIN RELIEF
17	0070-0163-003	1	Screened room to Axial interface box	RG223	44	13.411	BNC plug for RG223	BNC plug for RG223
18	0070-0163-004	1	Radial interface box to tube	RG316	8	2.438	FFA.00.250.CTA.C29Z + GMB:00.028.DA (BLUE STRAIN RELIEF)	BNC plug for RG316 + BLUE STRAIN RELIEF
19	0070-0163-005	1	Axial interface box to tube	RG316	20	6.096	FFA.00.250.CTA.C31	BNC plug for RG316
20		1	Rack output	RG316				BNC bulkhead jack PE4106 or similar
21		4	Interface box input & output	RG316				BNC bulkhead jack PE4106 or similar
Sweep Dri	ve	1	Dask to sereened		1		N type bulkhead jack	N type PE4329
22	0070-0164-001	1	room wall Positive	LMR-195	8	2.438	PE44528 red strain relief	red strain relief or similar
23	0070-0164-002	1	Rack to screened room wall Negaitive	LMR-195	8	2.438	PE44528 black strain relief	black strain relief or similar
24	0070-0164-003	1	Radial Interface box Positive	LMR-600	44	13.411	EZ-600-NMC-2-D or similar	EZ-600-NMC-2-D or similar
25	0070-0164-004	1	Screened room to Radial Interface box Negaitive	LMR-600	44	13.411	Pasternack EZ-600-NMC-2-D or similar	Pasternack EZ-600-NMC-2-D or similar
26	0070-0164-003	1	Screened room to Axial Interface box Positive	LMR-600	44	13.411	Pasternack EZ-600-NMC-2-D or similar	Pasternack EZ-600-NMC-2-D or similar
27	0070-0164-004	1	Screened room to Axial Interface box	LMR-600	44	13.411	Pasternack EZ-600-NMC-2-D	Pasternack EZ-600-NMC-2-D
28	0070-0164-005	1	radial Interface box to tube Positive	LMR-195	8	2.438	Pasternack red strain relief TNC 90° PE4678 or similar	N type PE4329 red strain relief or similar
29	0070-0164-006	1	Radial Interface box to tube Negative	LMR-195	8	2.438	Pasternack black strain relief TNC 90° PE4678 or similar	N type PE4329 black strain relief or similar
30	0070-0164-007	1	Axial Interface box to tube Positive	LMR-195	20	6.096	Pasternack TNC 90° PE4678 or similar	N type PE4329 or similar
31	0070-0164-008	1	Axial Interface box to tube Negative	LMR-195	20	6.096	Pasternack TNC 90° PE4678 or similar	N type PE4329 or similar
32		2	Rack output	RG402				Pasternack PE44707 or similar
33		8	Interface boxes input & output	RG402				Pasternack PE44707 or similar

Table 1Scorpion-Z cables and connector details part 1

ltem	Kentech part No.	QTY	use	Cable	Length of cable [feet]	Length of cable [m]	Left connector (nearer tube)	Right connector (nearer rack)
Sween mo	nitor							
34	0070-0165-001	1	Rack to screened room wall Positive	LMR-195	8	2.438	PE44528	N type PE4329 or similar
35	0070-0165-002	1	Rack to screened room wall Negative	LMR-195	8	2.438	PE44528	N type PE4329 or similar
36	0070-0165-003	1	Screened room to Interface box Positive	LMR-600	44	13.411	Pasternack EZ-600-NMC-2-D or similar	Pasternack EZ-600-NMC-2-D or similar
37	0070-0165-004	1	Screened room to Interface box Negative	LMR-600	44	13.411	Pasternack EZ-600-NMC-2-D or similar	Pasternack EZ-600-NMC-2-D or similar
38	0070-0165-005	1	Interface box to radial tube Positive	LMR-195	8	2.438	SMA 90°plug + red strain relief	N type PE4329 + red strain relief or similar
39	0070-0165-006	1	Interface box to radial tube Negative	LMR-195	8	2.438	SMA 90°plug + black strain relief	N type PE4329 + black strain relief or similar
40	0070-0165-007	1	Interface box to axial tube Positive	LMR-195	20	6.096	SMA 90°plug + black strain relief	N type PE4329 + red strain relief or similar
41	0070-0165-008	1	Interface box to axial tube Negative	LMR-195	20	6.096	SMA 90°plug + black strain relief	N type PE4329 or similar
42		8	Interface boxes	RG402				Pasternack PE44707 or similar
			mput & output					
Scorpion-Z	phosphor drive						DK 103 1032 CT 1-	
43.000	0070-0166-001	1.000	Rack to screened room wall	RG59 not RG179	8.000	2.438	DK 103 A023-600 Ø6.7 [finger safe]	SV 103 A023-600 Ø6.2
44	0070-0166-002	1	Radial interface box	RG59	44	13.411	[finger safe]	SV 103 A023-600 Ø6.2
45	0070-0166-003	1	Screened room to Axial interface box	RG59	44	13.411	SV 103 Z023-600 Ø6.2 [finger safe]	SV 103 A023-600 Ø6.2
46	0070-0166-004	1	Radial interface box to tube	RG179	8	2.438	FFR.0S.405.CLAEC33	SV 103 A023-600 Ø6.2
47	0070-0166-005	1	Axial interface box to tube	RG179	20	6.096	FFR.0S.405.CLAEC33	SV 103 A023-600 Ø6.2
48		1	Rack output (finger safe)	RG59			D 103 A023	
49		2	Interface box input				D 103 Z023	
50		2	Interface box output (finger safe)				D 103 A023	
			(80.00.0)					
Scorpion-Z	phosphor RETURN		Screened room wall to					
51	0070-0166-006	1	scope room wall	RG223	8	2.438	DK 103 Z023-600 Ø6.7 [finger safe]	Flying lead
52	0070-0166-007	1	to Screened room wall	RG223	44	13.411	SV 103 A023-600 Ø6.2 [finger safe]	SV 103 2023-600 Ø6.2 [finger safe]
53	0070-0166-008	1	Screened room to Axial interface box	RG223	44	13.411	SV 103 A023-600 Ø6.2 [finger safe]	SV 103 Z023-600 Ø6.2 [finger safe]
54	0070-0166-009	1	Radial interface box to tube	RG179	8	2.438	FFR.0S.405.CLAEC33***	SV 103 Z023-600 Ø6.2** [finger safe]
55	0070-0166-010	1	Axial interface box to tube	RG179	20	6.096	FFR.0S.405.CLAEC33***	SV 103 Z023-600 Ø6.2** [finger safe]
56 57		2	Interface box input Interface box output				D 103 Z023 D 103 A023	
Scorpion-Z	МСР		1	RG223]		1
58	0070-0167-001	4	Rack to screened room wall	(replaces RG174)	8	2.438	SHV Pasternack PE44080 or similar	SHV Pasternack PE4194 or similar
59	0070-0167-002	4	Screened room to Radial interface box	RG223	44	13.411	SHV Pasternack PE4194 or similar	SHV Pasternack PE4194 or similar
60	0070-0167-003	4	Screened room to Axial interface box	RG223	44	13.411	SHV Pasternack PE4194 or similar	SHV Pasternack PE4194 or similar
61	0070-0167-004	4	Radial interface box to tube	316 (replaces RG1	8	2.438	FFB.0S.403.CLAC27	SHV Pasternack PE44093 or similar
62	0070-0167-005	4	Axial interface box to tube	RG316 (replaces RG174)	20	6.096	FFB.0S.403.CLAC27	SHV Pasternack PE44093 or similar
63		4	Rack output	RG316			SHV Pasternack PE44093 or similar	
64		16	Interface box input & output	RG316			SHV Pasternack PE44093 or similar	
Scorpion-Z	HV ENABLED LEAD							
65	0070-0168	1	Rack to user	ro MP002342 [2 c	9.842	3.000	Unterminated	FFA.0S.302.CLAC32
66		1	Rack output					ERA.US.302.CLL
Scorpion-Z	INTERLOCK LEAD	1	Back to user	RG174	9 842	3 000	BNC plug for PC174	FEA 00 250 CTA C27
68	0070-0105	1	Rack output	1.01/4	J.042	3.000	Dive plug für KG1/4	ERA.00.250.CLL
Scornion-7	internal loop thour	trigger I	eads					
69	0070-0183	3	Rack internal loop through	RG316		0.084	Lemo FFA.00.250.CTAC31	Lemo
			leads			2.501		FFA.00.250.CTAC31

Table 2Scorpion-Z cables and connector details part 2

6.4 FUNCTIONALITY

The camera has several modes of operation but the important points to note are the electronic features that are present. These include the following:

- 1 Focussing for checking that the image on the cathode is in focus.
- 2 Flat fielding, for measuring the relative sensitivity of various parts of the detector system. The image of the cathode can be swept slowly across the detector.
- 3 Sweep modes
- 4 Sync. modes
- 5 Cathode blanking; the cathode to mesh voltage can be short circuited to blank the camera at the end of the sweep to stop large electron fluxes entering the camera. This is fairly fast, ~ tens of ns.
- 6 Crowbarring. The Focus voltages can all be reduced to near zero at the end of a sweep to protect the cathode and mesh from breakdown. This is slower than blanking, ~100 μs. The high voltage supplies are turned off when the crowbar fires to stop the voltage rising again as the crowbar switch turns off.
- 7 Electrical or optical triggering
- 8 Full-Frame Gating (FFGt) mode. Also referred to as Blankety Blank mode (BB mode).

Whilst in principal the system can do any combination of the various functions listed above, many will need further programming to implement. These are straightforward procedures but need to be done at the factory.

7. **OVERALL DESCRIPTION**

7.1 MECHANICS OF THE STREAK TUBE

The streak tube is a vacuum component. It should be kept clean, particularly on the surfaces exposed to the vacuum. Wear suitable gloves if possible when working on the streak tube.

The main vacuum interface is about halfway down the tube at the anode. Behind the anode is the drift tube and mounted along side this are the two connector boxes, one of which contains the blanking circuit. The blanking circuit short circuits the cathode and mesh (extraction grid) when triggered, effectively shuttering the tube. This is a fairly fast circuit, (tens of ns).

The connector boxes may be removed or partially removed to make fitting of a sensor module easier. See section 7.2.3 on page 22

The tube needs to be fitted with a photocathode and an extractor grid (mesh). The tube is supplied fitted with a LLNL supplied photo cathode pack which also accommodates a facility to mount a fibre optic fiducial system. As supplied the fibre optic fiducial cable is not installed as this makes packaging for shipping difficult.

When operating without the FO fiducial system the FO feed through needs to be plugged to seal the vacuum. The feed through is supplied with the plug fitted.

7.2 FITTING A MAX MODULE

The Max module is attached to the drift tube with four M5 bolts that screw from the tube and into the MAX module. In order to fit the bolts it will be necessary to remove the connector boxes. It is hard to fit a connector box with the fiducial fibre optic cable in place. Consequently the order of assembly should be:

- 1 Remove the connector boxes
- 2 Set the position of the scraper inside the drift tube.
- 3 Fit the sensor
- 4 Refit the connector boxes.
- 5 Fit the Fibre Optic fiducial assembly if required.

7.2.1 REMOVING THE CONNECTOR BOXES

Each connector box is held in position with four M3 screws. Remove the screws from one box then ease the box backwards and upwards (slightly) to miss the rear flange. Note that there are two high voltage leads entering the box from the streak tube. These are a little fragile as they are made from steel free RG402 cable. Each lead has a brass contact soldered to the end. This may catch on the edge of the hole as the box is withdrawn. Do not force it, but wriggle it if necessary. Each cable is fitted with a spring and a brass or aluminium alloy washer. Make sure these are in place before refitting the box.

7.2.2 SET THE POSITION OF THE SCRAPER INSIDE THE DRIFT TUBE.

The scraper ring (previously circular but now rectangular) prevents electrons that are highly deflected from bouncing of the drift tube wall and hitting the sensor.

The scraper ring position has been set to be suitable with a MAX module but may need resetting to make it suitable for the particular sensor that the user fits to the tube. The best way to find the optimum position is to use 3D modelling of the tube and sensor and look for relevant beam paths from the deflection plates to the sensor plane. Allow a little margin to avoid vignetting. A STEP file of the tube will be included with the tube data. The relevant dimension to measure in the model is the axial distance from the output face of the scraper to the output face of the drift tube where the sensor will be mounted. This should be set up before the sensor is mounted. The position is easily changed by loosening the four screws in the output face of the scraper and pulling or pushing the ring in the drift.



Figure 4 Schematic showing the axial position of the scraper. The drift tube is omitted for clarity.

4 screws clamp the scraper ring



Figure 5 Scraper ring mounting. View into rear end of streak tube before fitting the sensor. The scraper ring can be loosened and moved. If necessary it can be mounted in the reverse direction using the second set of threaded holes. There is no forced alignment of the orientation. this should be set by "eye" or measured.

tube to get the position correct. A vernier depth gauge will allow one to set it quite accurately and also square in the tube. Note also that the orientation w.r.t. the sensor should be retained. The fitted scraper aperture is 24 mm square. Different aspect ratio scraper rings are easily accommodated by replacing one aluminium alloy piece. This is left to the user, but we are happy to help. Note that the scraper



Figure 6 Mounting the Max Module adaptor.



Figure 7 Access to the camera mount holes



Figure 8 With the connector boxes removed Take care not to damage the four high voltage leads or to lose the washers and springs. Check that the brass end connections are in good order and well soldered to the cables. Note that these cables have copper inner conductors and are not as robust as most semirigid cables.



Figure 9 The fiducial fibre optic should be threaded very carefully through the Swage fitting and up to the photocathode pack. There is a slot in the grounded central lens to retain the fibre. Do not bend the fibre excessively. If you are unhappy about fitting it this way, loosen photocathode the pack and raise it as necessary to assist fitting the fibre. Tighten the swage fitting to achieve a vacuum seal on the fibre assembly.

assembly can be fitted either way around (w.r.t. the tube axis) with the clamp assembly either side of the scraper ring. Use which ever suits the application best.

7.2.3 FIT THE SENSOR

Kentech Instruments only has experience of fitting a phosphor or a MAX module. To fit a Max module four M5 screws are fitted through the holes shown in Figure 5 on page 20. They are mounted from the tube towards the Max module adaptor. Ensure that the "O" ring is fitted in the end of the drift tube.

The Max module is then attached to the adaptor. Again be ensure the "O" ring is fitted between the adaptor and the Max module. It is necessary to remove the cable supports of the max module in order to access the mount holes. Once the Max module is fitted the cable mounts and clamps can be refitted.

7.2.4 **REFIT THE CONNECTOR BOXES**

This is the reverse process of removing them. Be careful not to bend the high voltage connections coming out of the tube. These are difficult to replace and quite fragile as they are made from steel free semi rigid cable. Each connector box is held in place by 4 x M3 cap head screws.

7.2.5 FIT THE FIDUCIAL FIBRE OPTIC

The fibre optic fiducial is supplied by LLNL and is easily fitted to the streak tube before insertion into the vacuum system. Be aware that the fibre is fragile and should not be bent excessively. Also the tip must not be chipped.

- 1 Remove the knurled ring at the fibre optic vacuum feed through.
- 2 Remove the brass blocking piece. Keep this as it is useful to block up the hole for vacuum tests without the fibre fitted.

- 3 Make sure the "O" ring is still in place and slightly greased (Krytox[™] XHT-ACX silicone vacuum grease). Carefully thread the fibre through the bulkhead hole and feed the tip into the Fibre optic mount near the cathode. The fibre should fit in the slot in the grounded electrode. There should be enough space to fit the fibre without removing the connector box. It is difficult to refit the connector box with the knurled ring in place. The user may find that fitting the connector box after the fibre is OK.
- 4 Note that there is a "grounding" strap on the mirror of the FO fiducial system. It is not actually grounded as it connects to the Lens 1 element which is typically at ~11kV, however, it is important not to have pieces of metal in the tube assembly that are not connected to a specific potential. If left unconnected they can charge up via sprayed charge and then break down to some other element. On this build of Scorpion-Z the fiducial system was not fully implemented. The mirror is missing. Consequently the "grounding" strap has nothing to connect to. However, it is still fitted.



7.3 CONNECTIONS

There are 15 or 16 leads from the interface box to the streak tube assembly.

7.3.1 CONNECTING THE STREAK TUBE TO THE INTERFACE BOX

The following needs to be connected to the streak tube:

1 Two sweep leads.

TNC plug to 90°TNC plug at the tube end. The sweep will be towards the positive sweep cable.

- 2 Two Sweep monitor leads, SMA.
- 3 Blanking drive lead from the head unit to the "Fast Blanking Box"
- 4 Petzval corrector lead.
- 5 Focussing high voltage leads.

These four leads, cathode, mesh, lens1 (Crossover) and lens3 (Focus) are fixed into the high voltage module at the sockets marked. The ends that fit into the streak tube should be treated carefully. Each has a brass contact soldered onto its end. This engages in a spring loaded contact in the female connector. The leads use SMA clamping screws to hold them in place. If removing these leads do not pull hard, undo the SMA nuts and slowly remove the lead. If it catches wriggle it rather than pulling hard.

Note that there are a similar set of connections between the connector boxes and the streak tube. The tube is supplied with these connected. The boxes will need to be removed to access the screws that hold the sensor on the rear of the tube. When refitting the boxes make sure the brass washers and springs on the leads from the streak tube are not lost. Also make sure the leads are not bent significantly. In the event that one of the brass contacts becomes detached from its cable it is a little hard to repair.

7.3.2 CONNECTING THE MAX MODULE TO THE INTERFACE BOX

The following needs to be connected:

- 1 4 MCP drive leads
- 2 Phosphor leads 1 or 2 depending upon the Max module type.

7.3.3 CONNECTING THE INTERFACE BOX TO THE RACK UNIT

This has 13 connections. In addition there are 2 sweep and possibly a phosphor monitor that may go back to the screened box in which the rack unit sits. These 3 are not connected to the rack unit.

7.3.4 CONNECTING THE RACK UNIT TO THE OUTSIDE WORLD

There are the following connections from the rack unit to the outside world. Some are essential, others are for diagnetics or alternative modes.

- 1 power lead rear panel IEC connector
- 2 comms lead, either Ethernet on RJ45 or RS232 on a 9 way DIN connector.
- 2 triggers, pretrigger for the MCP and Phosphor ON and a sweep trigger. Currently the unit is configured so that they must both be either electrical or optical, not one of each.
- 4 Inhibit/enable. This is an input, short to enable the unit
- 5 HV enabled, this is an output. 2 pins are shorted when the high voltages are enabled.
- 6 Control module monitors, RF, MCP & phosphor ON trigger, sweep trigger.
- 7 Sweep module monitors, bias and sweep.
- 8 Max module driver, MCP and phosphor.

8. RADIATION HARDENED TECHNOLOGY

Scorpion-Z is designed to run in a high neutron radiation environment. The damage done by neutrons to electronics is different from that done by radiation in space. Many electronic components fail (even space rated ones) from fusion generated neutron damage. However, two groups of components have been found that are useful, the first group contains components that can withstand the neutrons and a second group that can survive neutrons if the power is not ON. The fast blanking switch uses components from the first group. The rack controller should be far enough away that neutrons are not an issue. the interface box contains only passive components that have been found to be resistant to neutrons.

9. STREAK CAMERA OPERATION

This section describes the general use of the X-ray streak camera. It assumes that the system is assembled as above and that the user has full control of the software, see section 14 on page 44

9.1 VACUUM REQUIREMENTS

The streak tube can only be used under a reasonable vacuum. The tube is not pumped but relies on the vacuum of the chamber it is connected to, in order to pump the tube. Care should be taken not to slow the pumping rate significantly with apertures and filters etc. For normal use with a phosphor the pressure should be below 10^{-4} mBar. For thin cathode to grid (mesh) spacers (under 2 mm) pump to under 10^{-5} mBar. If a Max module is fitted the user should use the recommendations of the supplier but generally lower is better. Our testing was done at ~ 10^{-6} mBar. When the max module is first pumped



Figure 10 Front panel of the rack unit

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Figure 11 Rear panel of the rack unit The EEPROM write protect button is at top right

after installation it is good not only to pump it for a long time (a few days) but also to apply the phosphor voltage gradually. With our testing we used a high impedance insulation tester with a current trip to check the phosphor breakdown voltage. Applying the voltage appears to cause gas to be emitted from the surfaces and it takes several attempts to get the hold off voltage high enough for operation.

9.2 PRINCIPAL OF OPERATION

The X-rays to be investigated, are incident on the photocathode and produce photoelectrons. The photoelectrons are imaged by the focussing electrodes, passing through the hole in the anode and form an image on the sensor module at the end of the streak tube. With a slit in front of the photocathode an image of the slit is formed on the phosphor. This image is swept across the phosphor by a ramp potential applied to deflection plates situated just beyond the anode hole. Position along the photocathode is magnified nominally by a factor of \sim 1.2 when used with a standard Kentech phosphor. The direction normal to this corresponds to time. There is an image inversion in the electron optics.

9.3 THE ELECTRON OPTIC FOCUSSING

Before the high voltage focussing supply is switched on the vacuum tube must be at a suitably low pressure, see section 12 on page 35. In order to obtain higher time resolution it will become necessary to increase the extraction field to >3 kVmm⁻¹ and under these conditions we recommend that the pressure be below 10⁻⁵ mBar. The extraction field can be adjusted without changing the voltages or focus by changing the spacer between the cathode and the extraction grid. If the unit is used at too high a pressure, electrical breakdown may occur which can damage the photocathode and/or extraction grid. There are many possible values of voltages that give focussed images and their values will depend upon the required magnification and the position of the sensor. It is up to the user either to experiment or preferably to simulate the electron lens to decide upon suitable values. The cathode is nominally at -14 to -15 kV and users should be aware not to place metallic objects near to the front end of the tube. As supplied the focus voltages are set to a set of values that gives a reasonably good focus on a Max module. The spatial resolution of the Max module is not as good as a standard phosphor.

Focussing is achieved most easily with the camera unswept and with a gold on quartz resolution cathode used in place of a normal one. This cathode is then illuminated with UV and the image of it focussed on the detector. The software has a mode of operation for doing this.

The cathode should be set to ~ 15 kV and then the other three high voltage potentials adjusted for good focus and desired magnification. The Petzval corrector voltage should also be set to give good spatial resolution at the image edges. Two further conditions need to be met. Firstly the voltage on Lens 1 (crossover) should be more negative than the mesh voltage. this ensures that any photoelectrons emitted by the mesh cannot arrive at the detector. Secondly it is also necessary that the cross over point be near the anode and sweep plates. By looking at the vignetting of the image of the cathode it is possible to see roughly when this condition is met. The software allows a voltage increment to be added to the existing voltage, the increment can be made negative to reduce the voltage. The camera is supplied with a software interface intended to be controlled through the IBC. If it is necessary to control the camera with a terminal then the unit can be placed into debug mode. In this mode focussing can be performed without the IBC. There is a **tweakfocus** command to aid adjusting the voltages more easily.



Figure 12 Four views of the tube showing the connections

9.4 CATHODE BLANKING

The unit is fitted with the option of fast photocathode blanking. This is achieved by short circuiting the cathode and mesh potentials with a high voltage switch. The switch is located in the one of the connector boxes attached to the side of the drift tube, see Figure 12 on page 28.

The box contains several high voltage FETs that are repeatedly triggered by a signal from the rack unit. The trigger signal is sent to arrive at the end of the sweep.

The blanking switch is vulnerable to short circuits that are not current limited. To improve the chances of the switch surviving breakdowns there are series current limiting resistors. However, if there is a breakdown to ground between the switch and the resistors the switch is not protected. It is therefore necessary to be very carefully with the insulation between the blanking circuit and the resistors. This is well protected at the time of shipping but if the cathode assembly is changed it is important that careful attention is paid to this issue.

9.5 CROWBAR

The unit is also fitted with a crowbar. This short circuits the cathode to mesh in the focus supply for long enough to turn off the supply. Normally this would be used in conjunction with the fast photocathode blanking.

The blanking and crowbarring operate in single shot mode as it is necessary to turn off the focus unit to stop the voltages recovering. In repetitive mode they do not operate.

10. THE RACK ELECTRONICS

The rack electronics consists of 4 main modules:

- 1 The control module
- 2 The sweep module
- 3 The Max module driver
- 4 The high voltage (HV) module

The first three of these are removable modules mounted at the top of the rack. The HV module is fixed in place in the lower half of the rack.

10.1 THE CONTROL MODULE

The control module deals with the user interface, the triggering and the ramp and delay generation. It accepts two triggers, the first switches on the MCP and phosphor of the Max module if either or both is in gated mode. The second trigger is for the ramp generator. The MCP off, fast blanking and crowbar are all generated internally at the end of the ramp with suitable delays so that the signals arrive at the streak tube at the relevant times with the cables provided or specified.

10.2 SWEEP MODULE

The sweep unit provides bias voltages as well as the ramp voltages to deflect the image. The bias voltage sets the start position of the sweep, normally off screen. It also sets the operation point of the ramp. The bias voltages have been preset to the optimum values for best sweep linearity. The system is capable of storing up to 16 sweep settings.

The sweep unit has several modes of operation, see Figure 25 on page 45. These enable the user to do the following:

- 1 nothing
- 2 normal sweep
- 3 normal sweep with modified start position for timing
- 4 flat fielding/focussing, a slow sweep for calibrating the area sensitivity of the sensor or focussing the tube.
- 5 Full-Frame Gating (FFGt) mode (Blankety blank)

A sweep monitor is provided for each plate. A fraction of the sweep signal to each plate is available to monitor the sweep signal see Figure 13 on page 32. The sweep can be made to run in either direction by swapping the sweep leads around. Time will run from the negative to positive sweep connection.

10.2.1 RATE LIMIT

The sweep unit has a hardware rate limit of 5Hz but the system is optimised for single shot use and at rates above 1Hz there may be some instability in the waveform.

The system is set up for use with the specified cables. It will drive cables of other lengths. However, if the round trip time of the sweep cables is less than the sweep duration some reflections may be present. These can be eliminated by careful setting up of the AWG sweep data but this needs to be done for the specific configuration used. Note also that the timing of the blanking and MCP OFF signals need to be tied to the end of ramp time at the sweep plates. This is discussed at 12.1 on page 35.

The bias voltages have the opposite polarity to the ramp voltages. As a convention the positive bias is the voltage on the sweep plate fed with the positive ramp and the negative bias the voltage fed to the plate that receives the negative ramp. Note that in flat fielding the bias voltages go from very negative to very positive on the positive plate and vice versa on the negative plate. During normal operation it is important that the potential at the centre of the sweep plates is close to zero otherwise the tube focussing can be degraded.

10.3 SWEEP GENERATION

Scorpion-Z uses a sweep circuit that was developed for the RSCE project at LLNL. This uses an arbitrary waveform generator and an amplifier to deliver very controlable ramps over a wide timescale range. This allows the user to compensate for waveform degradation in the long sweep cables. In addition the whole ramp waveform is easily movable within the arbitrary waveform record to accommodate delays. One feature that this system can offer is for changes in the sweep speed to be made about the screen centre, the screen edge or in principle about any other point. Ramps with variable rates or perhaps two linear rates are also possible. The ramp output can be delayed by moving the arbitrary waveform data within the output buffer. This is a fairly coarse delay of \sim 400ps. In addition there is a fine delay to cover the 400ps steps.

The arbitrary waveform is generated in the control module and fed to the sweep module where it is amplified and then split into a positive and negative ramp. The bias voltages are also added to each of the outputs. The RF monitor on the control module is a copy of the signal that is fed to the sweep module.

10.4 THE MAX MODULE DRIVER

The Max module driver is based upon the SPIDER intensifier module. This was designed to drive either a Max module or a normal image intensifier. The image intensifier mode is not supported on Scorpion-Z.

10.5 FULL FRAME IMAGING MODE (BLANKETY BLANK BB MODE)

A full frame imaging mode has been added for help with calibration of imaging sensors. This is also called Blankety Blank mode (BB mode). In this mode the negative sweep plate is grounded via a 100Ω resistor. The positive sweep plate can be switched between 0 volts and approximately 1400V in response to a trigger with the system in the relevant mode. The MCP & Phosphor trigger input should be used. This is DC coupled in this mode (it is normally AC coupled) and enables the user to drive the BB mode at the desired rate and dwell times. This mode can be enabled in focus/flat field mode in the ENERGIZE state.

BB mode is only available as a Level 3 command.



Figure 13 Tube wiring and blanking box

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11. USING THE CAMERA

11.1 MAGNETIC FIELDS

The electron optics are prone to image displacement under the influence of stray magnetic fields. To remove this effect a mumetal screen, which fits around the spool tube will probably be needed. This is similar to the DISC mumetal screen and is supplied by the user.

NOTE

The use of screws of magnetic materials in or near the photocathode assembly can give rise to image displacement. If it is necessary to replace screws ensure that they are of unplated brass or nonmagnetic stainless steel. The use of nickel (magnetic) plated brass screws has not been found to cause problems but we would advise against it. Similarly the residual magnetic field from stainless steel screws generated in the screw manufacturing process has not been found to be a problem.

The cables carrying the focus potentials to the electrostatic lens have copper inner conductors.

11.2 CATHODE AND MESH ASSEMBLY

The unit is delivered with a user supplied LLNL type cathode pack rather than the standard Kentech one. This facilitates easy removal of the cathode and mesh and also integrates with a fibre optic fiducial system.

11.3 FOCUS VOLTAGES

During testing the camera has been focussed with a standard Kentech phosphor placed at the standard distance from the sweep plates and anode. The system has 4 adjustable focus voltages plus the Petzval corrector. Whilst this facilitates zooming for use on a variety of sensors it means that there will be many focus conditions.

The following voltages produced a good focus on the Max module supplied for testing.

VPC VME VCR VFO VPE

15000 10616 10254 10286 900

We recommend simulating the camera electron optics and calculating the optimum focus voltages for the particular configuration to be used. This has proved very accurate. The 3D model of the tube will be provided for this.

11.4 DEFLECTION SENSITIVITY

With the voltages set as above and onto the standard Kentech phosphor, the defection sensitivity was $\sim \pm 18$ V/mm. I.e. the sweep plates require each to be at 18 volts (one positive and one negative to displace the image by 1 mm). Reducing the focus voltages proportionally by a factor 14/15 (i.e. cathode at -14 kV) gives a deflection sensitivity ~ 17 V/mm.

11.5 CROWBAR AND BLANKING

The blanking switch, mounted on the tube, shorts the cathode to mesh. The crowbar switch shorts the cathode to ground and also pulls the other lenses to ground via the zener chains that limit their difference voltages. There is no current trip on the focus power supply. In single shot mode the software turns







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off the focus supply at trigger time. In repetitive mode neither the blanking nor the crowbar switch is triggered. The delays for triggering the blanking and crowbarring are fixed in hardware.

12. INITIAL POWER-UP

It is necessary for the interlock to be set before the focus voltages can be turned on. It is intended that this be connected to relay contacts on a vacuum gauge. The focussing supply must not be turned on if the pressure is higher than 10^{-4} mBar. At extraction fields greater than ~1.5 kvmm⁻¹ (~3 mm spacer) it may be necessary to obtain a better pressure. We recommend that the camera first be timed and set up with a low extraction field (3 mm spacer between the cathode and mesh). Once the system is operating satisfactorily at this field the spacer can be reduced and the vacuum improved. Note that the pressure in the cathode to mesh gap is what is important, not that at some distance from the cathode.

When the power is first applied a small breakdown may occur as a result of absorbed gas being released under the influence of high electric fields. Note that the focus unit is set up to come on slowly. This has been found to help with breakdown problems.

It is recommended not to leave the camera powered up for long periods, e.g. while waiting for shots. An unexpected rise in the chamber pressure due to accidental venting or possibly pump failure could result in the destruction of the cathode and/or the extraction grid as the breakdown voltage falls in higher pressure gas.

12.1 PROCEDURE FOR TIMING THE STREAK CAMERA

In general the trigger signal should be timed so that it coincides with the X–ray signal on the photocathode, with allowance made for:

- i the flight time of electrons from the cathode to the sweep plates (approximately 1.7 ns)
- ii the time delay from triggering the control unit to the photocathode image reaching the middle of the screen. This time depends very much on the sweep speed in use and the distance from the rack electronics to the head and the set up of internal delays.
- iii the flight time of photons from the plasma to the cathode
- iv the relative timing of the electrical trigger and the start of the event at the target.

The Scorpion-Z streak tube is mounted a significant distance from the electronics. Consequently the timing has to take into account the various delay in the cabling. Further, there are 3 signals that need to arrive at the tube at the appropriate time, the ramp, the blanking trigger and the MCP off drive. The MCP on and Phosphor on are relatively slow and easily timed. These are linked to the other trigger input on the control module, labelled MCP and Phosphor ON. This needs to be triggered about 15 to $30 \ \mu s$ before the event.

The ramp needs to arrive at the tube next and then the Blanking trigger and MCP off need to arrive at the end of the ramp. However, the specified ramp cables use a foam dielectric which has a fast propagation velocity, whilst the other two signals are on solid dielectric. Consequently for a fast ramp, the blanking and MCP off signals have to be launched from the rack earlier than the ramp. The ramp needs then to be delayed so that it arrives at the correct time. With slower ramps the other two signals has to be delayed. A result is that the minimum trigger delay for the system is determined by the timing of the other two signals not by the ramp generator. The relative timing of all these signals is set up with a combination of delay cables and delay calibrations in the sweep records, see 14.13 on page 66.

11 of the 16 sweep records have been configured prior to shipment. The cables lengths used were exactly as prescribed in the updated Statement of Work and mirrored in Figure 3 on page 15. If there are any significant departures from this cabling then the timings may have to be reconfigured.

The timing of the MCP off signal is easy to determine as this is applied directly to the Max module and so should appear at the Max module 1.4ns after the end of the ramp. This allows for the time it takes the photoelectrons to move from the deflection plates to the Max module.

The timing of the ramp should be such that the event (assumed to be of very short duration) arrives at screen centre. So the photoelectrons representing the event need to be at the deflection plates at the time the sweep reaches screen centre. It takes around 1.5 ns for the electrons to move from the photocathode to the deflection plates.

The timing of the blanking pulse should be such that it arrives at the photocathode 1.5ns before the sweep ends. In practice it is not a very fast switch. The time the gate pulse takes to move from the blanking switch to the photocathode is around 1.5ns. The delay in the switch will be several ns and the rise time of the switch at least 10 ns. How accurately these need to be timed depend upon the type of event and how important post event blanking is.

If the streak tube is not fitted with an extraction grid or photocathode, then it is possible to run the focus potentials at atmospheric pressure. In this situation one can place a scope probe near the cathode and pick up the blanking signal. Do not run the Max module at atmospheric pressure.

It may be possible to pick up the blanking switch firing at the switch, possibly with its cover removed.

12.1.1 TRIGGER LOOP THROUGH CABLING

Three of the trigger signals are looped through connections on the hidden panel behind the front panel. This can help with diagnosing faulty triggering but it is also used to set the relative delays to the triggers for the fast blanking and the MCP off signals. These signals need to be nearly synchronous at the streak tube but there is significantly more delay in the MCP off pulse generation. These two signals are driven from the same trigger source. Consequently their relative delay has been fixed by careful setting of the length of the trigger loop through leads on the panel hidden behind the front panel.

See Figure 15 on page 37.

12.1.2 DELAY MODES

Scorpion-Z has several delay modes. One is such that the sweep rate can be changed and the timing to screen centre is unchanged. This enables the user to expand the time base about screen centre rather than the ramp start position. Whilst this may be useful in some instances it does require that the trigger delay for fast sweeps is necessarily long. There is also a delay mode whereby the time base expands about the screen edge or ramp start. Such modes have different delays to screen centre but are similar to conventional streak camera behaviour. The timing of the blanking and MCP off pulses is linked to the end of ramp and these will move with the change in sweep speed.

12.2 SWEEP TIMING DATA

The figures over the next few pages indicate of the timings of the different signals including the Ramp hold up pulser which is internal to the ramp generator and extends the period for which the ramp voltages stay high at the end of a sweep, so stopping retrace. Without this hold up pulser the time the ramps stays high will depend upon the capacitance of the cables to the sweep plates and consequently the length of the sweep cables.
Scorpion-Z timing diagram



Figure 15 Scorpion-Z timing flow diagram



Figure 16 Scorpion-Z timing graph

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Figure 23 Sweep trigger, sweep 10, Blanking trigger and MCP OFF from top to bottom.

The trigger is shown here negative going but it actually positive going. This shows the timing of the signals at

the end of the cabling, near the streak tube. It shows the timing of the end of ramp wrt the other two signals.

This shows the trigger delay of ~ 285 ns. Much of this is the length of the cables.



Figure 24 The trigger jitter of sweep 10 (the fastest) with delays set to minimum SD is \sim 9.9 ps

12.3 TESTS

The electron optics may be tested with either a DC X–ray source or a DC UV source, such as a mercury vapour lamp with quartz envelope. However, for optimum focus, the wavelength should match that to be used in the experiment as this affects the electron energy distribution of the photoelectrons. With an x-ray photocathode, the emitted electrons are secondary, i.e. generated by primary photoelectrons hitting the cathode structure and releasing several new electrons. For a UV photocathode the primary photoelectrons are used. It so happens that there is some similarity between the distribution of the electrons from a UV cathode and a gold x-ray one at 8keV, the peaks of the distribution are both at ~ 1.2eV. The electrons produced by x-rays have a longish tail going to higher energies. A suitable test resolution cathode should be used. LLNL and Kentech have designed these jointly and can offer advice.

A typical mercury vapour lamp operating 200 mm from the cathode will give a bright image on an intensified image. With suitable cathodes and reduced lamp to cathode spacing, it is possible to obtain moderately bright images without an intensification. Remember that the cathode is at -15 kV and that the lamp is probably grounded. It is possible to melt plastic substrate cathodes with some types of UV lamp. Also the UV output from UV lamps usually increases significantly as they warm up. UV light emitting diodes are coming on the market and may also be suitable. We have not yet tested any.

The focus potentials are changed with level 2 and 3 software commands.

With the DC source, the focus should be set for optimum image quality. The four potentials are interdependent and the optimum image quality is obtained by iterating between the various settings. The position of the crossover should also be close to the hole in the anode. If it is not, vignetting will occur. This is obvious when focussing the camera. Note that vignetting can occur if the crossover is either too far or too near the cathode. A suitable mid position must be found and this will be with the cross over roughly at the anode. This will ensure that the cross over is near the sweep plate assembly.

Stray magnetic fields may displace the image slightly. A mumetal screen may be adequate to remove this. Otherwise the magnetic field will have to be eliminated.

12.4 POSSIBLE FAULTS

12.4.1 NO DC IMAGE

Focussing unit not on or vacuum interlock not set. Insensitive cathode. Bad connections to cathode/mesh assembly. Short circuit between mesh and cathode. Breakdown of high voltage feed.

12.4.2 BAD FOCUS.

Poor connections to cathode/mesh.

Old/damaged cathode.

Poorly mated high voltage connector.

Fault in bias/sweep supply. (Confirm by disconnecting the sweep circuit completely, which should restore focus).

Focus voltages have drifted (unlikely).

Photocathode and mesh not normal to camera axis.

Image is due to x-rays going straight through the tube and exciting the phosphor. Check that no image is present with the focussing unit switched off. If necessary block the direct X-ray path.

12.4.3 NO STREAKED IMAGE.

Sensor triggering at wrong time, possibly from noise.

Sweep unit triggering at wrong time from noise.

Sweep feeds incorrectly connected.

Inadequate trigger signal causing jitter.

12.4.4 SPURIOUS BLOBS OF LIGHT.

Breakdown in chamber.

Pressure too high. Check vacuum and perform initial power up test.

Breakdown on shot. Plasma or target debris getting into electron optics. Is front of reentrant vessel adequately screened? It is wise to restrict the front aperture as much as possible and cover the X-ray line of sight with as thick a filter as will transmit the desired X-rays. Use the blanking and crowbarring options.

12.4.5 REDUCED SWEEP SPEED COMBINED WITH POSSIBLE LOSS OF FOCUS

Bad connection of one sweep lead. This reduces applied voltage ramp but also fails to a maintain zero potential in drift tube, hence affecting the focus.

12.4.6 JITTER PRESENT IN IMAGE.

Inadequate or irreproducible trigger signal. The electronics has a jitter of about 20 ps SD. It is necessary to provide a good and stable trigger source for the electronics. This may well not be easy but is left to the user. Kentech can advise about solutions to trigger problems but the subject is too wide for a discussion here.

N.B. Poor connections to the mesh or cathode will often result in an apparent drift in the focussing as the electrodes charge up.

13. PHOTOCATHODES

The cathode materials normally recommended for X-ray use are often heavy metal salts of iodine or bromine, or gold, but for high time resolution the energy spread from gold is too great. We recommend the use of potassium bromide or potassium iodide. Transfer the Photocathodes, if supplied, to an evacuated desiccator as soon as possible after receipt.

14. SOFTWARE INTERFACE

14.1 INTRODUCTION

The software used in Scorpion-Z uses a Forth operating system running on an M3 Cortex microprocessor in the rack control module. The program is stored in EEPROM and can be upgraded by a simple drag and drop process if the "Service only" USB port on the front panel is connected to a PC.

There are several modes for several different functions of the system. These are most easily understood by reference to Figure 25 on page 45. Within this figure the core operating states of the system can be appreciated along with how the system moves from one state to another and some of the operations and parameters that can be selected at each stage.

14.2 COMMAND LEVELS

There are three levels of commands:

Level 1 is for day to day use with a set up system.

Level 2 is for setting up the tube focus, timing and performing flat field tests.

Level 3 is for setting up system behaviour and sweep waveforms.

Levels 1 and 2 use a defined protocol with a strictly limited vocabulary and format of command and response. This is designed for easy interfacing with a suitable interface program. See section 14.10 on page 50.

Level 3 runs in "debug" mode. Here the system uses the Forth interpreter and replies with "OK" after commands are entered.

14.3 SOFTWARE VERSIONS AND SERIAL NUMBERS

The Level 3 command **scnz.hardware** should produce the following response:

SW version = 0 HV module # = 1 SW module # = 1 TC module # = 1 Job no. = 2104091

14.4 NON VOLATILE MEMORY

There are many parameters that need to be stored in non volatile memory. These include the basic calibration data for the various measurement systems, the system behaviour when certain conditions are encountered, the user parameters for use with a particular streak tube, etc.

There are two EEPROMs available to the user but only one should generally be adjusted. The other is in the HV module and this should not be changed unless the user is very clear about what they are doing. It is possible to do serious damage to a streak tube and possibly to the Rack control system if the parameters in there are changed inappropriately.

The second available EEPROM is in the Control module. Some information stored in this is unlikely to need changing frequently and so is protected by a write enable control. The control button is on the rear panel of the rack unit above the power inlet. It is not labelled.



Figure 25 Flow diagram for set up and operation in single shot and repetitive modes.

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Other parameters such as ramp waveforms may need more regular changing and are not write protected. The commands for saving the system state to the EEPROMs are in the sections below where it will also be indicated whether the write enable button needs to be depressed during the write cycle. See section 14.17 on page 73.

14.5 OPERATING STATE

There are four defined system operating states. These are:-

i. SAFE

The sweep pulser and sweep bias are off. The focus supplies are inhibited and all HV control adcs set to zero. Triggering is disabled

ii. STANDBY

The sweep pulser is ON but the biases are OFF.. The focus HV is inhibited and all control adcs set to zero³. The requested sweep data is loaded into the waveform buffer. Triggering is disabled or enabled depending on the trigger mode.

iii. ENERGISE

The sweep pulser and sweep bias are ON The focus HV supplies are ON and set to the requested focus values. Triggering is disabled

iv. ARM

The sweep pulser and sweep bias are ON The focus module HV supplies are ON Triggering is enabled.

14.6 SYSTEM OPERATIONAL VARIABLES

The operation of the Scorpion-Z system in the above operating states is also influenced and controlled by the operational variables. Operational variables are volatile and will have default values unless correctly configured after a reset or power cycling. See Figure 25 on page 45.

The following parameters are set with the command scnz!sysctrl, see section 14.10 on page 50.

- 1 Reserved
- 2 Trigger Source Defines the trigger source
- 3 Trigger Mode Defines the trigger behaviour
- 4 Sweep# Selects a set of sweep data
- 5 Camera Mode Defines the operating mode

14.6.1 TRIGGER SOURCE - PARAMETER 2

The trigger source flag selects either electrical or optical triggering.

Trigger Source	Behaviour
0	Both trigger inputs electrical - default
1	Both trigger inputs optical

3 In addition the unit will be in the STANDBY state after ENERGIZE has been requested but the high voltages have not yet reached their steady state. The HV active LEDs will flash as the voltages are ramped up.

14.6.2 TRIGGER MODE - PARAMETER 3

The trigger mode determines the behaviour of the trigger in the STANDBY operating state.

This allows the operation of the ramp generator and sweep bias to be checked without applying the focus voltages to the streak tube.

Trigger Mode	Behaviour
0	Trigger enabled in ARMED state only
1	Trigger enabled in ARMED and in STANDBY - default

14.6.3 SWEEP NUMBER - PARAMETER 4

The sweep data is stored in EEPROM in an area known as the sweep table. This is divided into 16 sweep records numbered 0 through 15. Each entry in a sweep record consists of the sweep waveform and a set of sweep control data. The sweep table has the capacity for 16 different data sets (records) (0 through 15), each set defining one sweep speed. The sweep control data includes a set of focus voltages, i.e. there is a independent set of voltages for each sweep#. The focus voltages need to be stored with the sweep data as the deflection sensitivity is dependent on them. The focus voltages may be slightly dependent upon the sweep speed due to dynamic defocussing In addition each sweep # includes a set of bias voltages for both normal and sync. operation.

The default sweep number at power on is 0.

14.6.4 CAMERA MODES - PARAMETER 5

The camera mode defines the mode of operation of the Scorpion-Z system.

There are five modes (0 through 4), a focus mode, 2 normal modes and 2 synchronisation modes:-

- 0 Focus/Flat field mode in which the focus of the streak tube may be check and modified, The focus supplies are operative but the fast sweep pulser is inhibited.
- 1 Repetitive (OPERATE) mode in which the camera may be repetitively triggered when armed.
- 2 Single shot (OPERATE) mode in which the camera may be triggered once after arming.
- 3 Repetitive SYNC mode in which the sweep starts on screen and in which the camera may be repetitively triggered when armed.
- 4 Single shot SYNC mode in which the sweep starts on screen and in which the camera may be triggered once when armed.

Note that there is no reduced scan mode set up although in principal this is possible.

Mode#

- 0 Focus/Flat field
- 1 Repetitive default.

Mode

- 2 Single shot
- 3 Repetitive Sync
- 4 Single shot Sync

14.7 DELAY CONTROL

The following delay control parameters are set with command **scnz!delctrl**, see section 14.10 on page 50. This takes 3 parameters:

- 1 Delay mode which point in the sweep record is used to set the sweep delay
- 2 Reserved
- 3 Sweep delay the amount of delay.

14.7.1 DELAY MODE - PARAMETER 1

The delay mode defines the point of the sweep waveform that is delayed by the sweep delay

Delay Mode# Behaviour

- 0 delay record start
- 1 delay screen start
- 2 delay screen centre

Note that sweep waveforms are stored in EEPROM with minimum delay (i.e. at the beginning of the sweep record) and the delays are then increased if necessary to accommodate the delay mode. Delays of the ramps are achieved by moving the ramp data within the waveform buffer (the section of RAM to where the waveform record is downloaded). This gives 400 ps resolution. In addition there is 400 ps of fine analogue delay. These two delay systems are integrated into the delay commands and are transparent to the user.

If mode 2 is chosen and a repetitive event is timed to screen centre at a slow sweep, then the sweep speed can be increased and the event will remain at screen centre. One can zoom in on the event. Note, however, that the trigger delay will be long as it has to accommodate the slowest sweep speed.

14.7.2 SWEEP DELAY - PARAMETER 3

This specifies the sweep delay to be applied in picoseconds. The range is 0 through 600,000.

14.8 MAX MODULE CONTROL

The Max module is controlled with the command **scnz!intctrl**, see section 14.10 on page 50. This command takes 3 parameters:

- 1 Intensifier mode
- 2 Phosphor voltage
- 3 MCP voltage

14.8.1 INTENSIFIER MODE PARAMETER 1

There are 5 modes for the Max module set by parameter 1:

- 0 MCP off, Phosphor off
- 1 MCP pulsed, Phosphor DC
- 2 MCP DC, Phosphor pulsed
- 3 MCP pulsed, Phosphor pulsed
- 4 MCP DC, Phosphor DC.

14.8.2 PHOSPHOR VOLTAGE, PARAMETER 2

This can take a value from 0 through 5500

14.8.3 MCP VOLTAGE, PARAMETER 3

This can take a value 0 though 900.

14.9 POWER UP SEQUENCE

After power cycling or a reset, the rack control module leaves the system in the SAFE state.

The results of this process should be read using the following two commands:

1 The rack controller hardware status read command **scnz@hardware**. This will return the software version number, the HV module serial number, the sweep module serial no., the control module serial no., and the Kentech job number. The state of the system can be verified with the Scorpion-Z status read command **scnz@status**.

A change of state can be requested by the IBC/user. The current, requested states are returned by **scnz@status** along with change of state activity.

This is not useful for normal operation of the system but it can be useful to read it for diagnostic purposes. After the power up sequence, the system state should eventually be SAFE. At this point there is no focus high voltage supply to the tube and the trigger is disabled.

The IBC/user should now set the operational variables using the Level 1 commands **scnz!sysctrl** and **scnz!delctrl**

scnz!sysctrl sets: Sweep#, Trigger Mode, Camera Mode, Trigger Source

scnz!delctrl sets Delay Mode and Delay

14.10 LEVEL 1 OPERATIONAL COMMANDS

For day to day use with a set up system.

There are two sets of commands names shown below. Remote control of the instrument should use the truncated form shown in blue below, all of which use the control protocol used on hDISC etc.

Commands shown in red are available in DEBUG mode only, they do not use the protocol as they are intended for an engineer to type. They are included because the names are less cryptic than the remote control forms, so I hope are an aid to understanding.

The following conventions are used in the command names:

!	store a value
(a)	fetch a stored value
a>	fetch a real time ADC value
>	hange to
0	reset

Name	scnz>safe
Explanation	Request system change to SAFE state
Format	sz_rqsf
returned value 1	r1 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable
Notes Will execute	in STANDBY, ENERGIZE, ARMED states

Name	scnz>standby
Explanation	Request system change to STANDBY state
Format	sz_rqsb
returned value 1	r1 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable
Notes Will execute This comman	in SAFE state nd clears interlock latches

Name	scnz>energize
Explanation	Request system change to ENERGIZE state
Format	sz_rqen
returned value 1	r1 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable
Notes Will execute This comman	in STANDBY state nd clears current trip latches

Name		scnz>arm
Explanat	ion	Request system change to ARMED state
Format		sz_rqar
returned	value 1	r1 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable
Notes	Will execute	in ENERGIZE state
r	This comman	d clears trigger latches

Name		senz!sysetrl
Explana	tion	store system control settings
Format		n1 n2 n3 n4 n5 sz!svsc
paramet	er 1	$p_1 = reserved$
paramet	er 2	$p_2 = Trigger source$
P		0 = electrical
		1 = optical
paramet	er 3	$p_3 = Trigger mode$
P		0 = trigger in ARM only
		1 = trigger in ARM or STANDBY
paramet	er 4	p4 = Sweep#
1		0 thru 15
paramet	er 4	p5 = Camera mode
1		0 = focus/flat field
		1 = repetitive
		2 = single shot
		3 = repetitive sync
		4 = single shot sync
returned	value 1	r1 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable
Notes	Will execute	in SAFE state
Name		scnz@sysctrl
Explana	tion	read back system control settings
Format		sz@sysc
returned	value 1	r1 = reserved
returned	value 2	r2 = Trigger source
		0 = electrical
		1 = optical
returned	value 3	r3 = Trigger mode
		0 = trigger in ARM only
		1 = trigger in ARM or STANDBY
returned	value 4	r4 = Sweep#
		0 thru 15
returned	value 5	r5 = Camera mode
		0 = focus/flat field
		1 = repetitive
		2 = single shot
		3 = repetitive sync
		4 = single shot sync
Notes	Read back of	f values set with sz!sysctrl

Name		scnz	delctr	1		
Explanation	1	store delay control settings				
Format		p1 p2	2 p3 s	z!delc		
parameter 1	l	p1 =	delay r	mode		
			0 = de	lay record s	start	
			1 = de	lay screen s	start	
			2 = del	lay screen c	entre	
parameter 2	2	p2 =	reserve	ed		
parameter 3	3	p3 =	delay i	in ps		
			0 thru	1 600 000		
returned va	lue 1	r1	0 => c	ommand co	ompleted, -1	=> unable
Notes Ex	ecutes in S	AFE	state			
0 = command completed, $-1 = $ unable						
Re	turns unabl	le in S	STANI	OBY, ENER	RGIZE and	ARM

Name	scnz@delctrl
Explanation	read back delay control settings
Format	sz@delc
returned value 1	r1 = delay mode
	0 = delay record start
	1 = delay screen start
	2 = delay screen centre
returned value 2	r2 = reserved
returned value 3	r3 = delay in ps
	0 thru 1 600 000

Notes Read back of values set with sz!delctrl

Name		scnz!intctrl			
Explana	tion	store intensifier control settings			
Format		p1 p2 p3 sz!intc			
paramet	er 1	p1 = intensifier mode			
		0 = MCP off, Phosphor off			
		1 = MCP pulsed, Phosphor DC			
		2 = MCP dc, Phosphor pulsed			
		3 = MCP pulsed, Phosphor pulsed			
		4 = MCP dc, Phosphor DC			
paramet	er 2	p2 = phosphor voltage (V) 0 thru 5500			
paramet	er 3	p3 = mcp voltage (V) 0 thru 900			
returned	value 1	r1 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable			
Notes	Executes in S	SAFE state			
0 = command completed, $-1 = $ unable		1 completed, -1 = unable			
Returns unable in STANDBY, ENERGIZE and ARM		le in STANDBY, ENERGIZE and ARM			

Name	scnz@intctrl
Explanation	read intensifier control settings
Format	sz@intc
returned value 1	r1 = intensifier mode
	0 = MCP off, Phosphor off
	1 = MCP pulsed, Phosphor DC
	2 = MCP dc, Phosphor pulsed
	3 = MCP pulsed, Phosphor pulsed
	4 = MCP dc, Phosphor DC
returned value 2	r2 = phosphor voltage (V) 0 thru 5500
returned value 3	r3 = map voltage (V) 0 thru 900
Notes Read back of	values set with sz!delctrl

Name		scnz@status
Explana	ation	Read status
Forma	t	sz@stat
returned	d value 1	r1 = machine state
		0 = SAFE
		1 = STANDBY
		2 = ENERGIZE
		4 = ARM
		r2 = requested state
		0 = SAFE
		1 = STANDBY
		2 = ENERGIZE
		4 = ARM
		r3 = remote task activity
		6 = changing to STANDBY
		7 = changing to ENERGIZE
		9 = changing to ARM
		12 = idle
		r4 =trigger latch
		0 = not triggered
		-1 = triggered
		r5 = current trip latch
		0 = ok
		-1 = tripped
		r6 = reserved
		r / = interlock laten
		0 = 0K
		-1 = interlock compromised
		18 – Teserved
Notes	The trigger l	atch signal is the logical OR of:
	sweep trig	g input latch
	MCP trig	input latch
	HV modu	ile internal trigger latch

Intensif Intensif More de	Intensifier module internal ON trigger latch Intensifier module internal OFF trigger latch More detail is returned by scnz@trigger	
The current trip late cathode mesh cu focus cu crossov phospho mcp cu	ch signal is the logical OR of current trip latch urrent trip latch urrent trip latch er current trip latch or current trip latch trent trip latch	
Notes More detail	il is returned by scnz@trip	
Name Explanation Format returned value 1	<pre>scnz@trigger Read trigger latches sz@trig r1 = Sweep user trigger input latch 0 = not triggered -1 = triggered r2 = MCP user trigger input latch 0 = not triggered -1 = triggered r3 = HV module internal trigger latch 0 = not triggered -1 = triggered r4 = Intensifier module internal ON trigger latch 0 = not triggered -1 = triggered r5 = Intensifier module internal OFF trigger latch 0 = not triggered -1 = triggered r6 = reserved</pre>	
Name Explanation Format returned value 1	<pre>scnz0trigger Reset all trigger latches sz0trig r1 0</pre>	

Notes Trigger latches also cleared by scnz>armed sz_rqar

Name	scnz@trip
Explanation	Read current trip latches
Format	sz@trip
returned value 1	r1 = cathode current trip latch
	0 = ok
	-1 = tripped
	r2 = mesh current trip latch
	0 = ok
	-1 = tripped
	r3 = focus current trip latch
	0 = ok
	-1 = tripped
	r4 = crossover current trip latch
	0 = ok
	-1 = tripped
	r5 = phosphor current trip latch
	0 = ok
	-1 = tripped
	r6 = mcp current trip latch
	0 = ok
	-1 = tripped

Name	scnz0trip
Explanation	Reset current trip latches
Format	sz0trip
returned value 1	r1 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable
Notes Trigger latch	es also cleared by scnz>energise sz_rqen

Name	scnz@interlock
Explanation	Read interlock status
Format	sz@intk
returned value 1	r1 = interlock input, true = open circuit, false = short circuit = ok
	r2 = reserved
	$r3 = interlock \ latch, \ true = tripped, \ false = ok$

Notes Interlock latches also cleared by scnz>standby sz_rqsb

Name	scnz0interlock
Explanation	Reset interlock latch
Format	sz0intk
returned value 1	r1 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable
Name	scnz@hardware

Name	scnz@hardware
Explanation	Read hardware status
Format	sz@hrdw
returned value 1	r1 = Kentech job number from rack controller

	r2 = trigger control unit serial no. (0 thru 15) r3 = sweep unit serial number (0 thru 15) r4 = HV unit serial number (0 thru 15) r5 = software version r6 = reserved r7 = reserved r8 = reserved
Name Explanation Format returned value 1	<pre>scnz@>temp Read measured remote temperatures sz@>tmp r1 = Processor module T1 (degrees C) r2 = Processor module T2 (degrees C) r3 = Sweep module T1 (degrees C) r4 =HV unit T1 (degrees C) r5 = HV unit T2 (degrees C) r6 = reserved r7 = reserved r8 = reserved</pre>
Name Explanation Format returned value 1	<pre>scnz@>Vtube Read measured sweep tube voltages sz@>vtb r1 = Petzval (V) r2 = Cathode (V) r3 = crossover (V) r4 = focus (V) r5 = mesh (V) r6 = Negative bias (V) r7 = Positive bias (V) r8 = reserved</pre>
Name Explanation Format returned value 1	scnz@>ltube Read measured sweep tube currents sz@>itb r1 = reserved r2 = cathode (0 thru 4095) r3 = crossover (0 thru 4095) r4 = focus (0 thru 4095) r5 = mesh r6 = reserved r7 = reserved r8 = reserved
Notes Measures loa plus crowbar	ad current plus current into $1.5G\Omega$ sense resistor to bias current on the photocathode

Name Explanation Format returned value 1	<pre>scnz@>int Read intensifier monitor ADCs sz@>int r1 = Phosphor output voltage r2 = MCP1 output voltage r3 = MCP2 output voltage r4 = MCP3 output voltage r5 = MCP4 output voltage r6 = Phosphor current r7 = MCP current r8 = reserved</pre>
Name Explanation Format returned value 1	<pre>scnz@>1diag Read measured diagnostics sz@>1dia r1 = 24V supply current in mA r2 = 12V supply current in mA r3 = Hold up pulser supply (V) r4 = Sweep pulser supply (V) r5 = reserved r6 = DAC rate count r7 = reserved r8 = reserved</pre>
Name Explanation Format returned value 1	<pre>scnz@>2diag Read measured diagnostic voltages sz@>2dia r1 = reserved r2 = reserved r3 = reserved r4 = reserved r5 = reserved r6 = EHT ref monitor r7 = reserved r8 = reserved</pre>
Name Explanation Format returned value 1	<pre>scnz@>3diag Read measured diagnostic voltages sz@>3dia r1 = 22V unregulated monitor r2 = 24V input monitor r3 = Blanking supply monitor r4 = Bias psu1 monitor r5 = Bias psu2 monitor r6 = reserved r7 = reserved r8 = reserved</pre>

Kentech Instruments Ltd., Isis Building, Howbery Park, Wallingford, Oxfordshire, OX10 8BD, U.K.

Name	scnz@>4diag
Explanation	Read measured diagnostic voltages
Format	sz@>4dia
returned value	r1 = MCP psu voltage
	r2 = MCP 1M voltage
	r3 = Phosphor psu
	r4 = reserved
	r5 = reserved
	r6 = reserved
	r7 = reserved
	r8 = reserved
Name	scnz@lswpctrl
Explanation	Read sweep control table part 1
Format	sz@lswc
returned value	r1 = swp eof
	r2 = swp hu f
	r3 = swp step
	r4 = swp lhs ps
	r5 = swp cen ps
	r6 = swp bias
	r7 = swp sync
	r8 = reserved
Notes These	e parameters are a function of the sweep#

They are set up and stored in eeprom with sweep waveform

Name	scnz@2swpctrl
Explanation	Read sweep ctrl table part 2
Format	sz@2swc
returned value 1	$r1 = swp_Vcathode$
	$r2 = swp_Vcrossover$
	$r3 = swp_V focus$
	$r4 = swp_Vmesh$
	$r5 = swp_Vpetzval$
	r6 = reserved
	r7 = reserved
	r8 = reserved
	r4 = swp_Vmesh r5 = swp_Vpetzval r6 = reserved r7 = reserved r8 = reserved

These parameters are a function of the sweep# Notes They are set up and stored in eeprom with sweep waveform

Name	scnz@wfmblock
Explanation	Read block of 16 samples from AWG buffer
Format	sz@wfmb
parameter 1	p1 = block number (0 thru 255)
returned value 1	r1 = sample value from address p1 x 16 + 0
	r2 = sample value from address p1 x 16 + 1
	r3 = sample value from address p1 x 16 + 2
	r4 = sample value from address p1 x 16 + 3
	r5 = sample value from address p1 x 16 + 4
	r6 = sample value from address p1 x 16 + 5
	r7 = sample value from address p1 x 16 + 6
	r8 = sample value from address p1 x 16 + 7
	r9 = sample value from address p1 x 16 + 8
	r10 = sample value from address p1 x 16 + 9
	r11 = sample value from address p1 x 16 + 10
	r12= sample value from address $p1 \times 16 + 11$
	r13= sample value from address $p1 \times 16 + 12$
	r14 = sample value from address p1 x 16 + 13
	r15 = sample value from address p1 x 16 + 14
	r16 = sample value from address p1 x 16 + 15

Notes This data is the data in the AWG waveform buffer generating the current sweep waveform.

It is a function of the sweep# and the user delay and delay mode. It is basically the data in the waveform table for the current sweep# in eprom but is right shifted to give the required coarse delay in 400ps steps.

14.11 LEVEL 2 COMMANDS TO ADJUST THE FOCUS & FLAT FIELD

Commands to adjust the focus of the system in situ and executing flat field measurements.

Name	scnz_focus
Explanation	Setup camera focus condition
Format	p1 sz_fcus
parameter 1	p1 = bias voltage for focus, range -800V to +800V
returned value 1	r1 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable
Notes Will execute	only in focus/flatfield mode

Name	scnz_flatarm
Explanation	Arm the camera system in flat field mode
Format	p1 sz_farm
parameter 1	p1 = pause in ms per step for flat field
returned value 1	r1 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable
Notes Will execute	only in focus/flatfield mode
Restores swe	ep bias to flatfield start condition

Name	scnz_flattrig
Explanation	Trigger the camera system in flat field mode
Format	sz_ftrg
returned value 1	r1 = sweep bias voltage on termination
returned value 2	r2 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable
Notes Will execute This comman Flat field swe character is re	only in focus/flatfield mode ad will not send a return value for several seconds until the sep has terminated. It will terminate prematurely if any further serial eceived.
Name	scnz_incvcathode
Explanation	add an increment to the cathode voltage
Format	p1 sz_+vpc
parameter 1	p1 = voltage increment, range +/-1000V
returned value 1	r1 = revised cathode voltage setting

Note Will execute only in focus/flatfield mode Changes only the ram value, will be lost on power up unless calibration saved

returned value 2

r2 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable

Name	scnz_incvmesh
Explanation	add an increment to the mesh voltage
Format	p1 sz_+vme
parameter 1	p1 = voltage increment, range +/-1000V
returned value 1	r1 = revised mesh voltage setting
returned value 2	r2 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable
Notes Will execute Changes only	only in focus/flatfield mode the ram value, will be lost on power up unless calibration saved

Name	scnz_incvfocus
Explanation	add an increment to the focus voltage
Format	p1 sz_+vfo
parameter 1	p1 = voltage increment, range +/-1000V
returned value 1	r1 = revised focus voltage setting
returned value 2	r2 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable
Notes Will execute	only in focus/flatfield mode
Changes onl	y the ram value, will be lost on power up unless calibration saved

Name	scnz_incvcrossover
Explanation	add an increment to the crossover voltage
Format	p1 sz_+vcr
parameter 1	p1 = voltage increment, range +/-1000V
returned value 1	r1 = revised crossover voltage setting
returned value 2	r2 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable
Notes Will execute Changes only	only in focus/flatfield mode y the ram value, will be lost on power up unless calibration saved

Name	scnz_incvpetzval
Explanation	add an increment to the petzval voltage
Format	p1 sz_+vpe
parameter 1	p1 = voltage increment, range +/-1000V
returned value 1	r1 = revised petzval voltage setting
returned value 2	r2 $0 \Rightarrow$ command completed, $-1 \Rightarrow$ unable
Notes Will execute	only in focus/flatfield mode
Changes only	y the ram value, will be lost on power up unless calibration saved

14.12 LEVEL 3 COMMANDS

These commands talk directly to the Forth interpreter using the Forth programming language and can be used manually with a terminal emulation program such as Hyperterminal.

A good general guide to Forth programming is <u>Programming Forth by Stephen Pelc</u> which is available on line in pdf format. However it is not necessary to have an in depth knowledge of Forth to use these commands.

Level 3 commands are only accessible in DEBUG mode. Debug mode is enabled/disabled using:-

+debug	- change into debug mode
-debug	- change into normal mode

Strictly +debug is a level 1 or 2 command but not included as it allows access to Level 3 commands and takes the unit out of the limited vocabulary mode.

In debug mode, the standard short form protocol commands can be used as in level 1 & 2 modes, but in debug mode the rack controller will also recognise the long form name of the function.

If any Forth macros are added the long form should be used.

For example the hardware status read command rc@hrdw will respond as before, but the system will also respond to the long form rc@hardware.

It will be observed that the returned parameters from rc@hardware are not formatted and printed, they are left on the data stack. The stack can be non destructively printed using the stack print command [.S] or the parameters can be printed one by one using the print command [].], which prints one parameter and drops it from the stack. Note that the returned parameters are in reverse order as the last returned parameter is at the top of the stack and will be the first one printed.

14.12.1 DECODED COMMANDS

scnz.delctrl	scnz@delctrl	sz@delc
scnz.intctrl	scnz@intctrl	sz@intc
scnz.status	scnz@status	sz@stat
scnz.lswpctrl	scnz@lswpctrl	sz@lswc
scnz.2swpctrl	scnz@2swpctrl	sz@2swc
scnz.hardware	scnz@hardware	sz@hrdw
scnz.trip	scnz@trip	sz@trip
scnz.interlock	scnz@interlock	sz@intk
scnz.trigger	scnz@trigger	sz@trig
scnz.>temp	scnz@>temp	sz@>tmp
scnz.>int	scnz@>int	sz@>int
scnz.>ldiag	scnz@>ldiag	sz@>ldia
scnz.>2diag	scnz@>2diag	sz@>2dia
scnz.>3diag	scnz@>3diag	sz@>3dia
scnz.>4diag	scnz@>4diag	sz@>4dia
scnz.>vtube	scnz@>vtube	sz@>vtla
scnz.>Itube	scnz@>Itube	sz@>itb

Several of the Level 1 & 2 commands have new versions under level 3 with parameter decoding.

These are typical responses to the commands:

scnz.delctrl

delay = 0delaymode = record start ok

scnz.intctrl

vmcp = 0 vphos = 0 intmode = MCP> dc off Phos> dc off ok

scnz.status

interlock latch = 0 hv_itripl =0 trig_l = 0 remtask state = Idle Requested state = Energized Remote state = Energized ok

scnz.1swpctrl

swp_sync = -250
swp_bias = -585
swp_cen_ps = 75960
swp_lhs_ps = 15740
swp_step = 0
swp_hu_f = -1
swp_eof = 28 ok

scnz.2swpctrl

swp_Vcorr = 568
swp_Vmesh = 10962
swp_VL3 = 9923
swp_VL1 = 11404
swp_Vcath = 14997 ok

scnz.hardware

SW version = 0 HV module # = 1SW module # = 1TC module # = 1Job no. = 2104091 ok

scnz.trip

mcpitrip_l = 0 phositrip_l = 0 Xovitrip_l = 0 Focitrip_1 = 0 meshitrip_l = 0 cathitrip_l = 0 ok

scnz.interlock

intlk latch = 0intlk input = 0 ok

scnz.trigger

mmBtrig_l = 0 mmAtrig_l = 0 hvtrig_l = 0 mcptrig_l = 0 swptrig_l = 0 ok

scnz.>temp

Processor T2 = 45Processor T1 = 48Sweep T1 = 39HV T2 = 45HV T1 = 39 ok

scnz.>int

imcp = 0iphos = 1Vmcp4 = 0Vmcp3 = 0Vmcp2 = 0Vmcp1 = 0Vphos = 7 ok

scnz.>1diag

dacrate = 0

Vsweep = 2 Vhold = 4 12V current = 136528V current = 275 ok

scnz.>2diag

eht vref = 10058 ok

scnz.>3diag

biaspsu2 = 1425 biaspsu1 = 333 550v mon = 51 24V mon = 23942 22V mon = 21173 ok

scnz.>4diag

Phos_psu_mon = 51 mcp_1meg_mon = 23942 mcp_psu_mon = 21173 ok

scnz.>vtube

>vpbias = -700 >vnbias = 700 >vmesh = 10961 >vfoc = 9924 >vxov = 11403 >vcath = 14996 >vpet = 567 ok

scnz.>itube

>imesh = 1096 >ifoc = 992 >ixov = 1140 >icath = 2999 ok

14.12.2 TUBE FOCUSSING - TWEAKFOCUS

The focus voltages can be set up by putting the system into focus mode (camera mode 0) and the ENERGIZE state. The voltages may be varied using Level 2 commands.

An alternative is to use the TWEAKFOCUS Level 3 command. This command is provided to simplify the task of focusing the streak tube. With the system in the ENERGIZE (2) state and with the camera mode set as FOCUS (0) this command runs a routine to adjust the voltage outputs from the focus supply. The parameters that can be modified are the current sweep#, Photocathode voltage, SLOT 1 voltage, SLOT 2 voltage, Focus voltage and Spare voltage.

Each sweep record in the sweep table contains a set of focus voltages and they are saved to EEPROM in the sweep tables with either **n** ee!swpctrl or **n** ee!sweep where **n** is the sweep table number (0 through 15). See section 14.17 on page 73. The sweep rate will depend upon the focus voltages so it is necessary to set up the focus voltages for each sweep rate. Often the focus voltages will be unchanged between sweep speeds, so there is a function to copy the focus voltages from one sweep record to another.

To set the focus voltages the camera mode should be focus/flat field (0) and the state should be ENERGIZE. If the focussing is to be done with a static image at tube centre then the bias voltage will have to be changed to zero with the command scnz_focus.

TWEAKFOCUS is activated by typing TWEAKFOCUS (cr).

The following keys are used to operate the function:

W or Q changes the selected parameter be adjusted. W to the right and Q to the left.

1 or 2 decrements/increments the set value by 1 $% \left(1-\frac{1}{2}\right) =0$

3 or 4 decrements/increments the set value by 10

5 or 6 decrements/increments the set value by 100

c or C will copy all the focus voltages of the selected sweep# to a clipboard

v or V will paste the clipboard into the focus voltages for the selected sweep#

- s or S will save the parameters in the sweep control block of the selected sweep# in EEPROM
- z or Z will undo the last paste operation.
- ESC will exit the routine

On exit the voltages will remain as they have been adjusted, but note that this data is volatile. It will be lost if the system power is cycled or the state is moved from SAFE to STANDBY (as this will download a sweep control table from EEPROM), unless it is explicitly saved in EEPROM using s or S within the TWEAKFOCUS command. An alternative is to use **n** ee!swpctrl to save the sweep control table for the record being adjusted (record = n).

Note that this part of the EEPROM is not write protected.

On exit from TWEAKFOCUS a parameter is returned on the stack. This is 0 for success and -1 for fail. Note that in the event of a fail, the routine is exited immediately.

If TWEAKFOCUS returns a non zero value it means the system state is not in ENERGIZE, and/or the camera mode is not FOCUS.

Note that if the bias voltage is adjusted with **scnz_focus** while tweaking the focus and then the new focus voltages are saved with **n ee!sweep**, the bias voltage will not be overwritten. This is intentional as the bias voltage always has to be adjusted to focus the tube.

An example session of adjusting the focus voltages is shown in Figure 26 on page 66.

Note that a set of focus voltages is required for each sweep record, hence the copy and paste commands.

tweakfocus

use q and w choose param then decrement/increment with 1 2 3 4 5 6 s to save c to copy v to paste z to undo paste SW# VPC VCR VFO VME VPE 0 14997 11404 9923 10962 568 ۸۸۸۸۸ SW# VPC VCR VFO VME VPE 0 14997 11404 9923 10962 568 ~~~~ SW# VPC VCR VFO VME VPE 0 14997 11404 9923 10962 568 ۸۸۸۸۸ SW# VPC VCR VFO VME VPE 0 14997 11404 9923 10962 568 ^^^^ SW# VPC VCR VFO VME VPE 0 14997 11404 9923 10962 568 ۸۸۸۸۸ SW# VPC VCR VFO VME VPE 0 14997 11404 9923 10962 568 ~~~~

Figure 26 Example of how to use the tweakers tweakfocus.

14.13 THE SWEEP TABLE DATA

The sweep table has 16 sweep records. Each sweep is represented in the EEPROM as a record of 8192 bytes. Each record contains a "sweep control table" and a "sweep waveform".

The sweep waveform which will be used by the AWG is kept as 4032 two byte sample values (11 bits used).

The remaining 128 bytes (that make up a sweep record) are used to store a block of parameters this is the "sweep control table". There is one sweep control table for each of the 16 sweeps that are stored.

Parameters in the sweep control table are:

swp_eof	- the eof sync delay in 6ns steps
swp_hu_f	- hold up pulser flag, true (-1) = enable, false (0) = disable
swp_lhs_ps	- time in ps from start of record to screen left
swp_cen_ps	- time in ps from start of record to screen centre
swp_bias	- bias in volts to use in repetitive and single shot modes
swp_sync	- bias in volts to use in repetitive sync and single shot sync modes
swp_vcath	- photocathode voltage in volts
swp_step	Sweep prebias - this shoud always be set to zero.

swp_vcr	- crossover voltage in volts
swp_vfo	- focus voltage in volts
swp_vmesh	- mesh voltage in volts
swp_vpe	- Petzval corrector voltage in volt

To set any of these parameters use the standard form, e.g. for the sweep hold up flag:

-1 swp_hu_f !

The value can also be read, e.g.

swp_hu_f @ .

Carriage returns have been omitted. The "@"fetches the value, the "." prints it.

14.13.1 CHANGING THE SWEEP WAVEFORM

When a sweep speed is selected the sweep waveform is copied from the sweep table in EEPROM to the waveform buffer RAM in the AWG.

The waveform buffer is 4096 two byte samples long, which is longer than the 4032 sample record in the sweep table. The deficiency of samples at the end of the waveform buffer is made good by duplicating the last sample of the record in the sweep table. So this should always be enough to deflect beyond screen right.

The position of the sweep table record when copied into the waveform buffer depends on the user delay setting and the delay mode. The samples are 400ps apart, and this is used as a means to vary the coarse delay. Any deficiency of samples at the start of the waveform buffer is made good by padding with zero samples. There is a fine delay hardware function that fills in the 400ps steps. The user delay is specified in ps and the system uses the two delay modes appropriately.

The way the user delay in ps is interpreted depends on the user delay mode, see section 14.7.1 on page 48.

With trigger mode 1 selected and in camera mode repetitive, the sweep waveforms can be characterised and adjusted in the STANDBY state without high voltages present on the streak tube (other than the sweep bias). The sweep waveform can be adjusted in the waveform buffer, then this can be copied to the user sweep table.

The sweep waveform should be adjusted at minimum delay. The system can add subsequently add delay to the waveform in the user sweep table relative to the sweep trigger as it copies the waveform to the AWG described above, but it can't remove delay, so the ramp data should be at the beginning of the record.

The following commands are provided to define and edit the sweep waveform:

XXX SETALL	Sets all 4096 samples in sample buffer to xxx
ZERO	Sets all samples to generate a zero waveform
+RAMP	Produces a rising linear ramp over all samples
-RAMP	Produces a falling linear ramp over all samples
xx %WFM	Scale the waveform by $xx \%$ and send to the output ⁴
XX TWEAK	Interactively tweak individual samples
x n !SAMPLE	Set sample at address n (0 through 4095^3) to x (0 through 2047^3)
	(note this does not write the waveform to the FPGA)

⁴ Note that the data has a maximum value of 2047 and is an integer. The address must be inside the permitted range. No error messages are issued for incorrect data.

n ?SAMPLE	Print value of sample address n
?WFM	Print the waveform buffer as a formatted list of DAC values
TXWFM	Transmit current waveform in binary from buffer to terminal
RXWFM	Receive a binary waveform from terminal to buffer.
?SUMWFM	Print the checksum of the waveform modulus 2 ¹⁶
WFM>FPGA	Copy the waveform buffer to the FPGA and output to the DAC on receipt of a trigger

Note that **WFM>FPGA** is needed in conjunction with the **!SAMPLE** command. Figure 27 on page 70 shows how the data is manipulated.

Any sweep waveform set up in this way is volatile and will be lost at power down unless explicitly saved in EEPROM. Further, a change from SAFE state to STANDBY state will overwrite the waveform buffer with the data in the EEPROM at the sweep table specified by the scnz!sysctrl command. The waveform buffer can be saved to EEPROM with the command

n ee!wfm

where $\mathbf{n} =$ the sweep record to be used.

The EEPROM used for sweep data and user variables is not write protected, i.e. there is no need to operate any write protect button.

14.13.2 CHANGING THE SWEEP CONTROL TABLES

The sweep control table parameters other than focus voltages should also be setup at this stage.

The 12 parameters in a sweep control table can be modified under Level 3 commands simply by saving a new value in the variable and then saving the table into the relevant sweep record with **n ee!swpctrl** where **n** is the record number (i.e. the sweep number). However, the focus voltages are more easily set up with either Level 2 commands or with TWEAKFOCUS, see section on page 63

There are also tweakers for the end of frame sync. delay.

Tweak_eof

Both take values from 0 through 255 representing 6ns steps

On launch two numbers are presented, the former is the increment and the latter the current value the parameter is set to.

Use the keys "1" & "2" respectively to decrease and increase the increment

Use the keys "3" & "4" to respectively to subtract or add the increment to the current value.

The "ESC" key will exit the routine.

The block of sweep control table parameters can be saved to EEPROM with

n ee!swpctrl

where \mathbf{n} = the sweep record to be used, see section 14.17 on page 73.

The waveform and control data from the sweep table, defined by the user variable sweep# (normally set within the scnz!sysctrl command), is read by the system on transition from the SAFE to STANDBY states and used to setup the system appropriately.

14.13.3 SWEEP HOLD UP PULSER

At the end of the ramp the sweep plates will be brought back to their initial state by the bias supply. The supply has a high source impedance and so will take a long time to recharge long sweep cables. However, shorter sweep cables will recharge more quickly. There is a hold up pulser in the Sweep module that holds the voltage difference on the plates high (and in the deflected state) for ~ 1.2 ms. The pulse is not equal and opposite (as the ramps are) due to loading by the sweep monitor on the sweep module that loads the positive ramp more than the negative. Imbalance after the sweep is not a important.

The hold up pulser can be enabled and disabled and there is a flag (swp_hu_f) in the sweep control table to reflect this. It should be set up in the usual way when setting up a ramp, see 14.13 on page 66.

14.13.4 SWEEP BIAS VOLTAGES AND SWEEP DELAYS

The above does not allow the setting of the sweep bias voltages for sweep modes (Camera modes 1 though 4). These must be explicitly set by loading the required value into the appropriate variable prior to saving the sweep control data with **n** ee!swpctrl or **n** ee!sweep.

The required voltages will depend on the streak tube and sweep speed. Generally the bias voltage has to be large enough to hold the start point off screen. Also if the ramp has any non linearities, then the bias voltage can be used to set the most linear part at screen centre.

The voltages have to be obtained empirically for each streak tube used.



* When the state is changed to standby the waveform in the EEPROM is copied to the waveform buffer. This will overwrite any changes made with "**tweak**" or "!**sample**".

The **tweak** and **!sample** functions can be used in both the safe and standby states.

Note that **!sample** does not update the FGPA so if the command is executed in standby mode while viewing the waveform it will be necessary to execute the **wfm>fpga** command to see changes to the waveform.

Figure 27 The structure of the waveform generation

The bias voltage used in sync. mode is often zero. This puts the sweep start at screen centre. However,, a more useful place is at the left hand side of the screen. I.e. the starting side, as this gives a longer temporal record. Sync. modes help with timing of the sweep trigger. If an undeflected image appears, the trigger was too late or absent. If no image appears the trigger was to early or no signal was received. Assuming no errors this can give a binary search procedure for the correct trigger timing. It is good practice to check for error occasionally otherwise the binary search can be lead astray.

The sweep delays also have to be set. These need to be measured for a particular sweep set up and streak tube. The delay to sweep centre is just the time it takes the ramp to get to be equal but opposite to the bias voltage, i.e. the plate voltage is zero.

If the streak tube deflection sensitivity is well known, then the time to any point on the screen can be measured and the time to screen left can be set.

14.14 BEHAVIOUR CONTROLLED BY CALIBRATION VARIABLES

In the following several calibration variable may be changed. In all cases they are changed by the following procedure:

Type the following;

x variable_name ! cr

where x is the new value and there is a space before the "!" which represents "store" in Forth.

The new value is in volatile memory and should be saved to EEPROM by the appropriate ee! command.

14.14.1 FLAT FIELD RANGE

The flat field routines available under level 2 commands require the start and end bias voltages to be set. These are stored in two variables:

ffstartbias

ffendbias

The end bias must always be more positive than the start bias.

The factory default values are -700 and +700 volts respectively but these may not be suitable for all streak tubes.

The variables are changed in the usual way:

x ffstartbias ! cr

y ffendbias ! cr

Where x and y are the starting and ending bias voltages in volts (integers) in the range -800 to +800 Note that the step in the flat fielding sweep is 1 volt and the pause per step is in the range 1 to 1000 ms.

The values stored here are in volatile RAM. To save to EEPROM use the command

ee!tc_cal cr

Note that the write protect button will need depressing for this.

14.14.2 CURRENT TRIP BEHAVIOUR

There is a current trip on each of the HV outputs. The spare output current trip is only active when the "USE SPARE" link is fitted in the HV unit. The same trip level is applied to all outputs and is in arbitrary units 0 though 4095. The trip is enabled or disabled according to the variable

Uitrip_en

It takes values, True (-1) = enable, False (0) = disable.

There are two different levels applied, these are defined by the variables

```
itripl_startup
itripl_steady
```

itripl_startup is the value loaded for the soft start of the HV module and will be the higher of the two values.

After soft start has finished there is a programmable delay before the lower value **itripl_steady** is loaded and used. A delay is necessary as it takes time for voltages in the Gate module to stabilise.

The delay is defined in milliseconds by the variable

Tsettle

It is unlikely that they will need changing. They can be saved to EEPROM with **ee!tc_cal**, this needs the write protect button depressed.

Uitrip_en and Tsettle are in the control unit calibrationvariables and use **ee!tc_cal**. **itripl_statup** and **itripl_steady** are in the HV calibration variables and use ee!hc_cal. Both of these need the write protect button depressed to overwrite the data.

14.15 SLOW SCAN FOR FLAT FIELDING

In order to do a flat field calibration of the sensor Scorpion-Z has a slow scan mode, see "Name scnz_flatarm" on page 60 and subsequent commands.

The sequence of operations for a slow scan is (the text on the left, in red, is what is entered +cr but it is not echoed on normal mode):

safe		Make sure camera is in Safe mode
0 0 01 0 0 sz!sysc	{0 0 1 0 0 sz!sysc;0 }	Set camera mode to zero = flat field/slow scan Trigger inputs - electrical Trigger mode 1 - may not be necessary
sz_rqsb sz_rqen sz@stat	<pre>{sz_rqsb;0 } {sz_rqen;0 } {sz@stat;1 ;2 ;7 ;0 ;0 ;0 ;0 ;0 ;0 }</pre>	Request standby mode Request energise - turns on focus voltages Check machine state is energised (currently not), it takes around 10 seconds for the voltages to come up
sz@stat sz@stat	{sz@stat; 1 ;2 ;7 ;0 ;0 ;0 ;0 ;0 } {sz@stat; 2 ;2 ;12 ;0 ;0 ;0 ;0 ;0 }	re-check re-check - now energised.
5 sz_farm	{5 sz_farm;0 }	Arm slow scan - beam moves off screen to start position. Scan rate will be 5 ms per step
sz_ftrg;700

Trigger slow scan - there is no response until the command completes. The bias remains at 700 volts on the positive ramp at the end of the scan (-700 on the negative ramp).

14.16 FULL-FRAME GATING, BLANKETY BLANK

This mode, described at 10.5 on page 31, can be enabled in focus mode with the Scorpion-Z in the ENERGIZE state.

scnz_+bblank - start Bblank operation scnz -bblank - stop Bblank operation

Both these commands return a flag on the stack,

0 = successful

-1 = unable to execute

scnz_?bblank - query state of Bblank state

14.17 SUMMARY OF COMMANDS FOR SAVING TO EEPROM

There are several commands for saving different parts of the overall calibration and set up to the EEPROMs.

The commands can only be executed in debug mode and all take the form:

ee!xxxx where xxxx defines which group of parameters is to be saved. Some have a preceding parameter, i.e. **n ee!xxx**

14.17.1 LIST OF ee! COMMANDS

To execute a write protect save the button on the rear panel should be depressed while executing the command.

ee!hv_cal	write protected
ee!tc_cal	write protected
ee!sw_cal	write protected.
ee!user	NOT write protected
n ee!swpctrl	NOT write protected
n ee!wfm	NOT write protected
n ee!sweep	NOT write protected

ee!hv_cal HV calibration data. We recommend not changing as it could result in damage to components.

ee!tc_cal For saving calibration data

ee!sw_cal Saves the sweep module calibration

ee!user This is useful for saving a set up as default that otherwise would require the execution of the control commands for the system and the delay (scnz!sysctrl & scnz!delctrl).

It saves the following parameters:

U_intmode 0 = allways off 1 = pulsed mcp 2 = pulsed phosphor

	3 = pulsed both
	4 = DC on
UVmcp	MCP voltage
UVphos	Phosphor voltage
Utrigmode	0 = all triggers only enabled in armed state
	1 = all triggers enabled in standby and armed
Utrigsourc	0 = electrical trigger
	-1 = opto trigger
Ucammode	0 = focus/flatfield
	1 = repetitive
	2 = single shot
	3 = repetitive sync
	4 = single shot sync
Usweep#	0 through 15
Udelmode	0 = delay record start
	1 = delay screen start
	2 = delay screen centre
Udelay	delay in ps
n ee!swpctrl	Saves all the current sweep control table parameters to entry n (0 through 15) in the sweep table
n ee!wfm	saves the contents of the current waveform buffer to entry n (0 through 15) in the sweep table
n ee!sweep	saves all the current sweep data to entry n (0 through 15) in the sweep table i.e. it does n ee!swpctrl and n ee!wfm
These three com	mands are show in Figure 28 on page 77

15. MAINTENANCE, REPAIR AND REFURBISHMENT

The tube may require occasional cleaning if the x-ray source deposits significant debris on the tube. Solvent cleaners are recommended. Pump down times after such cleaning may take somewhat longer.

All parts of the tube (as supplied) are easily replaceable although damage to the 4 high voltage feeds will require some careful work.

We recommend that no repair, other than the replacement of the photocathode and/or extraction grid (mesh), of the tube be carried out with the fiducial fibre optic in place.

Repair or replacement of the wiring to the extraction grid (mesh) and photocathode should be done in the knowledge that the blanking circuit is vulnerable to breakdown at certain points, see Figure 13 on page 32. Insulation should not be compromised at these vulnerable points.

Always take care removing the two connector boxes as a failure of the vacuum feed through cable (see Figure 7 on page 21, is a significant repair.

16. TUBE PERFORMANCE IN STATIC TESTING

The streak tube was focussed using UV light onto a gold on quartz resolution photocathode. The photocathode is specifically designed to help focus this tube and has been designed by a collaboration of LLNL and Kentech staff. The photocathodes are manufactured by Luxel in Washington State.

Focussing was first carried out using a Kentech phosphor. A fibre optically coupled CCD camera was used to record the images. However, this only had an 18 mm FO input. Further the FO input was a taper to match an 18mm input format to a smaller CCD chip. Consequently the sensitivity near the edges of the input face is reduced as the fibre are longer and more curved. The illumination of the photocathode is also quite non uniform as it is necessary to mount the UV lamp close to the photocathode to get enough signal.

The images are, however, adequate to check the focus and the magnification as a function of position along the length of the photocathode.

Focussing was then carried out using the supplied Max module. There was no obvious difference in the optimum focus voltages. The axial position of the MCP input face is 0.76mm of the phosphor detection surface according to the 3D modelling.

The spatial resolution achieved with the max module is significantly worse than with a simple phosphor.

Some results are shown in Figure 29 on page 80 and Figure 30 on page 81.



Figure 28 The commands for saving the 2 parts of a sweep record to the EEPROM

17. SWEEP DATA

One the following 6 pages are shown 11 stored ramps numbered 0 through 10. The scope traces also show the calculated limits of the sweep range on the tube. These limits are obtained by measuring the tube deflection sensitivity and assuming a 39 mm active window.

During ramp setup the voltage about witch the ramp is most linear is measured and this is used to set the bias voltage for the particular ramp. Then the time to screen centre is measured so that the expand about screen centre function can be implemented.

The ramp data, the bias voltage, the focus voltages and the delays to screen edge and screen centre are stored in a sweep record.

18. PACKING LIST

The numbers refer to Kentech part numbers.

1 off 0010-0159 Scorpion-Z Streak camera for the Z machine comprising of the following:

Electronics package

 1 off 0060-0154 Scorpion-Z rack unit (serial No. J2104091-1) fitted with: 0060-0169 Control module for Scorpion Rack controller 0060-0170 Sweep module for Scorpion Rack controller 0060-0171 Max module for Scorpion Rack controller 0060-0172 HV module for Scorpion Rack controller

Interface boxes

2 off 0060-0155 Scorpion-Z interface box (serial No. J2104091-3 & J2104091-4)

Cables

4 off	0070-0161-002 Scorpion-Z HV leads interface box to tube
4 off	0070-0161-004 Scorpion-Z HV leads rack to interface box
1 off	0070-0162-002 Scorpion-Z corrector leads rack to interface box
1 off	0070-0162-004 Scorpion-Z corrector leads interface box to tube
1 off 1 off	0070-0163-002 Scorpion-Z blanking trigger lead rack to interface box 0070-0163-004 Scorpion-Z blanking trigger lead interface box to tube
1 off 1 off	0070-0164-005 Scorpion-Z sweep leads interface box to tube positive 0070-0164-006 Scorpion-Z sweep leads interface box to tube negative
1 off 1 off	0070-0165-005 Scorpion-Z sweep monitor leads tube to interface box positive 0070-0165-006 Scorpion-Z sweep monitor leads tube to interface box negative
1 off	0070-0166-002 Scorpion-Z phosphor leads rack to interface box
1 off	0070-0166-004 Scorpion-Z phosphor leads interface box to tube (max module)
1 off	0070-0166-007 Scorpion-Z phosphor return leads interface box to rack
1 off	0070-0166-009 Scorpion-Z phosphor return leads tube (max module) to interface box
4 off	0070-0167-002 Scorpion-Z MCP leads rack to interface box
4 off	0070-0167-005 Scorpion-Z MCP leads interface box to tube (max module)
1 off	0070-0168 Scorpion-Z HV enabled lead
1 off	0070-0169 Scorpion-Z interlock lead

1 off US style power lead - IEC

Streak Tube

1 off 0030-0252 HDISC Tube later than J2012101,

special options:

SMA sweep monitor variant (serial No. J2104091--2) fitted with free issued LLNL photocathode pack

Miscellaneous

1 off CD with manual and test data



Figure 29 Data for the measurement of deflection sensitivity.

Kentech Instruments Ltd., Isis Building, Howbery Park, Wallingford, Oxfordshire, OX10 8BD, U.K.



Variation of the magnification along the slit direction with position over a 13 mm range. 5.75 pixels per cycle to 5.89 pixels per cycle.





Figure 30 Variation in magnification along the slit.

Kentech Instruments Ltd., Isis Building, Howbery Park, Wallingford, Oxfordshire, OX10 8BD, U.K.



Figure 31 Focussing with the Max module.

Kentech Instruments Ltd., Isis Building, Howbery Park, Wallingford, Oxfordshire, OX10 8BD, U.K.



Figure 32 Sweep 0



Figure 33 Sweep 1



Figure 34 Sweep 2



Kentech Instruments Ltd., Isis Building, Howbery Park, Wallingford, Oxfordshire, OX10 8BD, U.K.



Figure 36 Sweep 4



Figure 37 Sweep 5



Figure 38 Sweep 6



Kentech Instruments Ltd., Isis Building, Howbery Park, Wallingford, Oxfordshire, OX10 8BD, U.K.



Figure 40 Sweep 8



Kentech Instruments Ltd., Isis Building, Howbery Park, Wallingford, Oxfordshire, OX10 8BD, U.K.



Figure 42 Sweep 10





Figure 43 Top is sweeps 0 through 5, lower is sweeps 5 through 10



Figure 44 All sweeps. The lower figure is with delay about centre active